

AUGUST 16, 2006

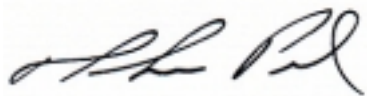
TEST REPORT #206273-2

MIXED FLOWING GAS TESTING

PART NUMBERS

SFM-125-02-S-D-A/TFM-125-02-5-D-A

SAMTEC, INC.



APPROVED BY: THOMAS PEEL  
PRESIDENT AND  
DIRECTOR OF TEST PROGRAM DEVELOPMENT  
CONTECH RESEARCH, INC.

REVISION HISTORY

DATE	REV. NO.	DESCRIPTION	ENG.
8/16/06	1.0	Initial Issue	TP



## CERTIFICATION

This is to certify that the evaluation described herein was designed and executed by personnel of Contech Research, Inc. It was performed with the concurrence of Samtec, Inc., of New Albany, IN who was the test sponsor.

All equipment and measuring instruments used during testing were calibrated and traceable to NIST according to ISO 10012-1 and ANSI/NCSL Z540-1 and MIL-STD-45662 as applicable.

All data, raw and summarized, analysis and conclusions presented herein are the property of the test sponsor. No copy of this report, except in full, shall be forwarded to any agency, customer, etc., without the written approval of the test sponsor and Contech Research.



Thomas Peel  
President And  
Director Of Test Program Development  
Contech Research, Inc.

TP:cm



## SCOPE

To perform Mixed Flowing Gas testing on the QSE/QTE, SFM/TFM and SSM/TSM connectors as manufactured and submitted by the test sponsor Samtec, Inc.

## APPLICABLE DOCUMENTS

1. Unless otherwise specified, the following documents of issue in effect at the time of testing performed form a part of this report to the extent as specified herein. The requirements of sub-tier specifications and/or standards apply only when specifically referenced in this report.
2. Cisco "Qualification of Electrical Connectors" specification, EDCS-164608, Rev. A1.
3. Standards: EIA Publication 364

## TEST SAMPLES AND PREPARATION

1. The following test samples were submitted by the test sponsor, Samtec, Inc., for the evaluation to be performed by Contech Research, Inc.

### Part Number

- a) SFM-125-02-S-D-A
  - b) TFM-125-02-S-D-A
2. Test samples were supplied assembled and terminated to test boards by the test sponsor.
  3. Test boards for mounting test samples were supplied by the test sponsor.
  4. The test samples were tested in their 'as received' condition.
  5. Unless otherwise specified in the test procedures used, no further preparation was used.



TEST SELECTION

1. See Test Plan Flow Diagram, Figure #1, for test sequences used.
2. Test set ups and/or procedures which are standard or common are not detailed or documented herein provided they are certified as being performed in accordance with the applicable (industry or military) test methods, standards and/or drawings as specified in the detail specification.

SAMPLE CODING

1. All samples were coded. Mated test samples remained with each other throughout the test group/sequences for which they were designated. Coding was performed in a manner which remained legible for the test duration.
2. The test samples were coded in the following manner:

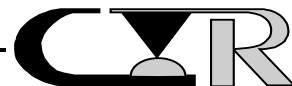
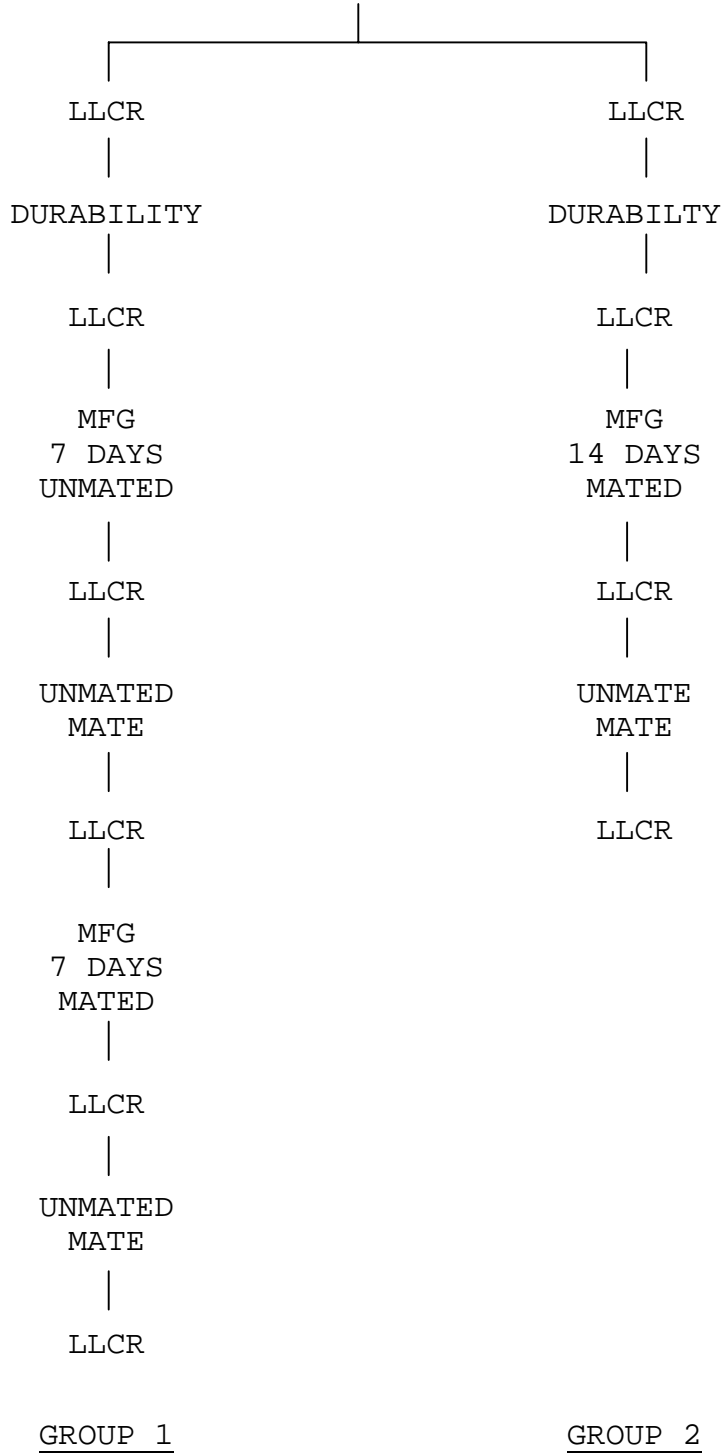
<u>Spec#</u>	<u>Part Numbers</u>	<u>Description</u>	<u>Sample ID#'s</u>	
			<u>Group A</u>	<u>Group B</u>
1062	SFM-125-02-S-D-A/ TFM-125-02-S-D-A	Unidentified	58 - 77	78 - 85



**FIGURE #2**

TEST PLAN FLOW DIAGRAM

SAMPLE PREPARATION



**DATA SUMMARY**

<b><u>TEST</u></b>	<b><u>REQUIREMENT</u></b>	<b><u>RESULTS</u></b>
<b><u>GROUP 1</u></b>		
<b>LLCR</b>		
-SFM/TFM	RECORD	9.7 mΩ MAX.
<b>DURABILITY</b>		
-SFM/TFM	NO DAMAGE	PASSED
<b>LLCR</b>		
-SFM/TFM	+10.0 mΩ MAX.CHG.	+2.0 mΩ MAX.CHG.
<b>MFG, 7 DAYS UNMATED</b>		
-SFM/TFM	NO CORROSION	PASSED
<b>LLCR</b>		
-SFM/TFM	+10.0 mΩ MAX.CHG.	+6.5 mΩ MAX.CHG.
<b>UNMATE/MATE CYCLE</b>		
-SFM/TFM	NO DAMAGE	PASSED
<b>LLCR</b>		
-SFM/TFM	+10.0 mΩ MAX.CHG.	+3.4 mΩ MAX.CHG.
<b>MFG, 7 DAYS MATED</b>		
-SFM/TFM	NO CORROSION	PASSED
<b>LLCR</b>		
-SFM/TFM	+10.0 mΩ MAX.CHG.	+3.9 mΩ MAX.CHG.
<b>UNMATED/MATE CYCLE</b>		
-SFM/TFM	NO CORROSION	PASSED
<b>LLCR</b>		
-SFM/TFM	+10.0 mΩ MAX.CHG.	+4.3 mΩ MAX.CHG.
<b><u>GROUP 2</u></b>		
<b>LLCR</b>		
-SFM/TFM	RECORD	+8.3 mΩ MAX.CHG.
<b>DURABILITY</b>		
-SFM/TFM	NO CORROSION	PASSED
<b>LLCR</b>		
-SFM/TFM	RECORD	+1.2 mΩ MAX.CHG.



**DATA SUMMARY**

<u><b>TEST</b></u>	<u><b>REQUIREMENT</b></u>	<u><b>RESULTS</b></u>
<u><b>GROUP 2-continued</b></u>		
<b>MFG, 14 DAYS MATED</b>		
-SFM/TFM	NO CORROSION	PASSED
<b>LLCR</b>		
SFM/TFM	+10.0 mΩ MAX.CHG.	+1.4 mΩ MAX.CHG.
<b>UNMATED/MATE CYCLE</b>		
-SFM/TFM	NO CORROSION	PASSED
<b>LLCR</b>		
-SFM/TFM	+10.0 mΩ MAX.CHG.	+1.2 mΩ MAX.CHG.





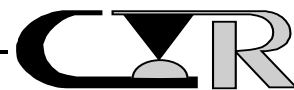
## EQUIPMENT LIST

ID#	Next Cal	Last Cal	Equipment Name	Manufacturer	Model #	Serial #	Accuracy	Freq. Cal
102	11/21/2006	11/21/2005	Data Acquisition Unit	Hewlett Packard	3421A	2338A02027	±. 5 %Of Indicated	12mon
150			Drill Press Stand	Craftsman	25921	N/A	N/A	N/A
208			Analyzer	Columbia Scientific	SA285E	JC006	See Manual	N/A
215			Scanner Main Frame	Keithley Co.	706	439246	See Manual	Ea Test
244	9/19/2006	9/19/2005	Micro-Ohm Meter	Keithley Instr.	580-1	467496	See Cal Cert	12mon
340			X-Y Table	NE Affiliated Tech.	XY-6060	N/A	N/A	N/A
529			Computer	ARC Elect.	486-40	N/A	N/A	N/A
543	1/10/2007	1/10/2006	Analytical Balance	Ohaus Co.	AP250D	MO9198	± .4mg	12mon
569			Regulator	Matheson	3810-660	DV001914F	N/A	Ea Test
579			Regulator	Matheson Co.	3810-330	DV002147F	N/A	N/A
586			Regulator Valve	Matheson Co.	3810-330	262813	See Manual	N/A
673	7/24/2007	7/24/2006	Microohm Meter	Keithley Co.	580	0681911	See Cal Cert	12 mon.
1032			Computer	Magitronic	486DX4	100VL	N/A	N/A
1045	7/10/2007	7/10/2006	Microohm Meter	Keithley	580	708216	See Cal Cert	12mon
1077			Pentium 2 Processor	Intel	B80523P350512E	98480250-0450	N/A	OOS
1125	8/1/2007	8/1/2006	Microohm Meter	Keithley	580	451920	See Cal Cert	12 mon.
1219			Computer	ARC Co.	350	350	±2%	N/A
1287	10/28/2006	4/28/2006	Temp Humid Transmitter	Vaisala	HMP233	WO430048	See Cert	6mon
1297			MFG Control Panel	Contech Research	N/A	N/A	C1686A	N/A
1298			MFG Chamber	Contech Research	64 Cu Ft	N/A	N/A	N/A
1326			Gas Regulator	Matheson	3810-660	R77108	N/A	N/A
1334			Oxidant Moniter	Mast	724-5	2923	See Manual	N/A



# TEST RESULTS

## GROUP 1



PROJECT NO.: 206273-2                      SPECIFICATION: CISCO EDCS-164608

PART NO.: See page 4                      PART DESCRIPTION: Plug / Receptacle  
Connector

SAMPLE SIZE: 20 samples/PN      TECHNICIAN:      MOB

START DATE:      6/28/06                      COMPLETE DATE:      7/11/06

ROOM AMBIENT:      23°C                      RELATIVE HUMIDITY:      58%

EQUIPMENT ID#:      1125, 1219

LOW LEVEL CIRCUIT RESISTANCE (LLCR)

PURPOSE:

1. To evaluate contact resistance characteristics of the contact systems under conditions where applied voltages and currents do not alter the physical contact interface and will detect oxides and films which degrade electrical stability. It is also sensitive to and may detect the presence of fretting corrosion induced by mechanical or thermal environments as well as any significant loss of contact pressure.
2. This attribute was monitored after each preconditioning and/or test exposure in order to determine said stability of the contact systems as they progress through the applicable test sequences.
3. The electrical stability of the system is determined by comparing the initial resistance value to that observed after a given test exposure. The difference is the change in resistance occurring whose magnitude establishes the stability of the interface being evaluated.

PROCEDURE:

1. The test was performed in accordance with EIA 364, Test Procedure 23 with the following conditions:
2. Test Conditions:
  - a) Test Current                                      : 100 milliamps maximum
  - b) Open Circuit Voltage                              : 20 millivolts
  - c) No. of Positions Tested                              : 25 per test sample



REQUIREMENTS:

Low level circuit resistance shall be measured and recorded.

-----  
RESULTS:

1. The following is a summary of the data observed:

LOW LEVEL CIRCUIT RESISTANCE  
(Milliohms)

<u>SFM/TFM ID#</u>	<u>Avg.</u>	<u>Max.</u>	<u>Min.</u>
58	7.5	9.0	7.0
59	7.0	8.5	6.3
60	7.6	9.7	7.0
61	7.4	7.7	7.1
62	8.1	9.2	7.6
63	7.2	7.9	6.8
64	7.5	7.8	7.1
65	7.5	8.8	7.0
66	7.0	7.5	6.6
67	7.4	8.1	6.9
68	7.2	7.7	6.9
69	6.7	7.3	6.2
70	7.1	7.8	6.8
71	7.5	8.2	7.0
72	7.4	8.4	6.9
73	7.7	8.5	7.0
74	7.2	8.1	6.8
75	7.6	9.0	6.9
76	7.3	7.9	6.6
77	7.3	8.4	6.8

2. See the following data files for individual data points:

-SFM/TFM : 206273-258 through 206273-277



PROJECT NO.: 206273-2                      SPECIFICATION: CISCO EDCS-164608

PART NO.: See page 4                      PART DESCRIPTION: Plug / Receptacle  
Connector

SAMPLE SIZE: 20 samples/PN      TECHNICIAN:      MOB/GL

START DATE:      7/11/06                      COMPLETE DATE:      7/12/06

ROOM AMBIENT:      23°C                      RELATIVE HUMIDITY:      55%

EQUIPMENT ID#:      150, 529, 340, 673, 1125, 1219

DURABILITY

PURPOSE:

1. This is a preconditioning sequence which is used to induce the type of wear on the contacting surfaces which may occur under normal service conditions. The connectors are mated and unmated a predetermined number of cycles. Upon completion, the units being evaluated are exposed to the environments as specified to assess any impact on electrical stability resulting from wear or other wear dependent phenomenon.
2. This type or preconditioning sequence is also used to mechanically stress the connector system as would normally occur in actual service. This sequence in conjunction with other tests is used to determine if a significant loss of contact pressure occurs from said stresses which in turn, may result in an unstable electrical condition to exist.

PROCEDURE:

1. The test was performed in accordance with EIA 364, Test Procedure 09.
2. Test Conditions:
  - a) No. of Cycles                      :      25
  - b) Rate                                      :      1.0 inch per minute
3. The test samples were assembled to special holding devices and attached to the manual cycling equipment.
4. The test samples were axially aligned to accomplish the mating and unmating function allowing for self-centering movement.



PROCEDURE: -continued

5. Care was taken to prevent the mating faces of the test samples from contacting each other.
6. All subsequent variable testing was performed in accordance with the procedures previously indicated.

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REQUIREMENTS:

1. There shall be no evidence of physical damage to the test samples so tested.
2. The change in low level circuit resistance shall not exceed +10.0 milliohms.

-----  
RESULTS:

1. There was no evidence of physical damage to the test samples as tested.
2. The following is a summary of the data observed:

CHANGE IN  
LOW LEVEL CIRCUIT RESISTANCE  
(Milliohms)

<u>SFM/TFM ID#</u>	<u>Avg. Change</u>	<u>Max. Change</u>
58	-0.1	+0.2
59	+0.1	+0.9
60	-0.1	+0.8
61	-0.3	+0.2
62	-0.3	+0.3
63	-0.4	+0.0
64	-0.2	+0.1
65	-0.2	+0.3
66	-0.2	+0.0
67	-0.4	-0.1
68	-0.2	+0.3
69	+0.2	+1.1
10	-0.2	+0.3
71	-0.3	+0.2
72	-0.3	+0.0
73	+0.5	+2.0
74	-0.2	+0.1
75	-0.1	+0.2
76	-0.1	+0.4
77	-0.2	+0.2



RESULTS: -continued

3. See the following data file for individual data points:

-SFM/TFM : 206273-258 through 206273-277



PROJECT NO.: 206273-2 SPECIFICATION: CISCO EDCS-164608

PART NO.: See page 4 PART DESCRIPTION: Plug / Receptacle Connector

SAMPLE SIZE: 20 samples/PN TECHNICIAN: MOB/GL/SR

START DATE: 7/17/06 COMPLETE DATE: 8/9/06

ROOM AMBIENT: 22°C RELATIVE HUMIDITY: 52%

EQUIPMENT ID#: 102, 208, 215, 244, 529, 543, 569, 579, 586,  
673, 1032, 1045, 1077, 1125, 1219, 1287, 1297,  
1298, 1326, 1334

MIXED FLOWING GAS

PURPOSE:

1. To determine the impact on electrical stability of contact interfaces when the test samples are exposed to a mixed flowing gas environment. Said environment is based on field data simulating typical, severe, non-benign environments. Said exposure is indicative of expected behavior in the field.
2. Mixed flowing gas tests (MFG) are environmental test procedures whose primary purpose is to evaluate product performance under simulated storage or operating (field) conditions. For parts involving plated contact surfaces, such tests are also used to measure the effect of plating degradation (due to the environment) on the electrical and durability properties of a contact or connector system. The specific test conditions are usually chosen so as to simulate, in the test laboratory, the effects of certain representative field environments or environmental severity levels on standard metallic surfaces.

PROCEDURE:

1. The test environment was performed in accordance with EIA 364, Test Procedure 65 with the following conditions.



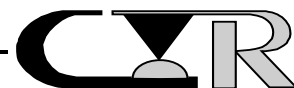


PROCEDURE: -continued

2. Environmental Conditions:

- a) Temperature : 30°C ± 1°C
- b) Relative Humidity : 70% ± 2%
- c) Cl<sub>2</sub> : 10 ± 3 ppb
- d) NO<sub>2</sub> : 200 ± 50 ppb
- e) H<sub>2</sub>S : 10 ± 5 ppb
- f) SO<sub>2</sub> : 100 ± 20 ppb
- g) Exposure Time : 14 days
- h) Mating Conditions : Day 1-7, unmated  
: Day 8-14, mated
- i) Mounting Conditions : Mounted

- 3. The test chamber was allowed to stabilize at the specified conditions indicated.
- 4. After stabilization, the test samples and control coupons were placed in the chamber such that they were no closer than 2.0" from each other and/or the chamber walls.
- 5. The test samples were handled in a manner so as not to disturb the contact interface.
- 6. After placement of the test samples in the chamber, it was allowed to re-stabilize and adjusted as required to maintain the specified concentrations and conditions.
- 7. The test chamber was monitored periodically during the exposure period to assure the environmental conditions as specified were maintained.
- 8. During the exposure, resistance measurements were taken at specific intervals and in the following sequence.
  - a) Place the test samples in the test chamber.
  - b) At each designated measurement period, remove the test units from the test chamber. The test samples were exposed to room ambient for two hours prior to making measurements.
  - c) Measure and record low level circuit resistance measurements.
  - d) Upon completion of the measurements, place the test units back into the test chamber until the next measurement interval or until completion of the test duration.



PROCEDURE: -continued

9. The samples were tested in the following sequence:

- a) MFG, Day 1-7, Unmated (receptacle exposed)
- b) LLCR
- c) Unmate/Mate, 1 Cycle
- d) LLCR
- e) MFG, Day 8-14, Mated
- f) LLCR
- g) Unmate/Mate, 1 Cycle
- h) LLCR

10. All subsequent variable testing was performed in accordance with the procedures previously indicated.

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REQUIREMENTS:

- 1. There shall be no evidence of damage or corrosion to the test samples as exposed which will cause mechanical or electrical malfunction of the said samples.
- 2. The change in low level circuit resistance shall not exceed +10.0 milliohms.

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RESULTS: See next page



RESULTS: -continued

1. The following is a summary of the data observed:

MAXIMUM CHANGE IN  
LOW LEVEL CIRCUIT RESISTANCE  
(Milliohms)

<u>SFM/TFM ID#</u>	<u>Day 1-7</u>		<u>Day 8-14</u>	
	<u>Unmated</u>	<u>1 cycle</u>	<u>Mated</u>	<u>1 cycle</u>
58	+0.2	+0.4	+0.3	+1.2
59	+6.5	+2.2	+2.4	+4.3
60	+0.3	+0.5	+0.4	+1.6
61	+2.5	+2.2	+3.2	+3.3
62	+1.9	+0.4	+1.0	+2.3
63	+1.3	+0.5	+0.5	+1.6
64	+1.8	+1.3	+0.6	+1.6
65	+0.4	+0.7	+0.6	+1.5
66	+0.4	+0.7	+0.7	+2.4
67	+0.7	+0.6	+0.3	+0.3
68	+2.3	+0.5	+0.6	+2.6
69	+0.8	+1.9	+1.1	+2.7
70	+1.0	+0.4	+0.4	+1.6
71	+1.0	+0.5	+0.4	+1.4
72	+1.0	+0.6	+2.1	+2.5
73	+4.5	+3.4	+3.9	+5.2
74	+1.8	+1.4	+1.1	+2.9
75	+1.9	+0.6	+0.7	+3.4
76	+2.3	+2.1	+2.0	+2.6
77	+0.4	+0.4	+0.7	+3.1

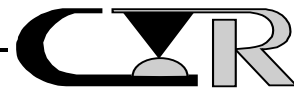
2. See the following data file for individual data points:

-SFM/TFM : 206273-258 through 206273-277

3. Five copper coupons were placed in the chamber. Upon removal said coupons were evaluated via weight gain technique with the following results:

<u>Coupon No.</u>	<u>WEIGHT GAIN (<math>\mu\text{gm}/\text{cm}^2/\text{Day}</math>)</u>	
	<u>Day 1-7</u>	<u>Day 8-10</u>
1	14	12+
2	13	13+
3	13	14
4	15	14
5	12+	14+

Requirement: 12 to 16  $\mu\text{gm}/\text{cm}^2/\text{Day}$



# LLCR DATA FILES

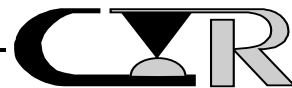
## FILE NUMBERS

### SFM/TFM

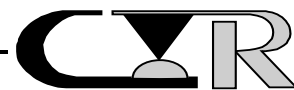
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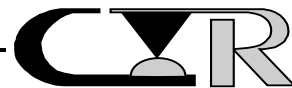
Low Level Contact Resistance						
Project:	206273-2				Spec:	EIA 364, TP23
Customer:	Samtec				Subgroup:	A
Product:	SFM-125-02-S-D-A/TFM-125-02-S-D-A				File #:	206273-258
Description:	ID# 58					
Open circuit voltage:	20mv				Current:	100ma
Delta values units: milliohms						
Temp °C	23	23	22	22	22	22
R.H. %	60	56	50	50	51	51
Date:	29Jun06	07Jul06	25Jul06	25Jul06	04Aug06	04Aug06
Pos. ID	Initial	25X	7D MFG	1X	7D MFG	1X
			Unmated		Mated	
1	7.3	0.1	-0.1	0.2	0.1	0.1
2	7.1	0.1	0.0	0.2	0.0	0.1
3	7.0	0.0	0.0	0.4	0.3	0.4
4	7.3	0.0	-0.2	0.2	0.0	0.1
5	7.3	-0.1	-0.2	0.1	0.0	-0.1
6	7.3	0.1	0.0	0.1	0.0	0.4
7	7.0	0.1	-0.2	0.1	0.0	0.1
8	7.1	-0.3	-0.2	0.1	-0.1	0.1
9	7.2	0.0	0.0	0.1	0.0	0.3
10	7.2	-0.1	0.0	0.2	0.1	0.3
11	7.4	-0.3	-0.2	-0.1	-0.1	1.2
12	7.2	-0.2	0.0	0.1	0.1	0.5
13	7.4	-0.3	0.0	0.4	0.2	0.7
14	7.4	-0.2	0.2	0.0	0.0	0.9
15	7.5	-0.1	-0.2	-0.1	-0.2	-0.2
16	7.7	-0.1	-0.2	-0.1	-0.3	-0.1
17	7.4	0.0	0.0	0.1	0.0	0.1
18	7.5	0.2	0.0	0.2	0.1	0.3
19	8.8	-0.4	-0.3	-0.2	-0.3	-0.4
20	7.4	-0.1	-0.1	0.1	0.1	0.0
21	7.4	-0.2	-0.1	0.1	0.1	0.3
22	7.5	0.0	-0.1	0.0	-0.1	0.0
23	9.0	-1.1	-1.4	-1.4	-1.4	-1.3
24	7.7	-0.2	-0.2	0.2	0.0	0.1
25	7.6	-0.2	0.0	0.2	0.1	0.1
MAX	9.0	0.2	0.2	0.4	0.3	1.2
MIN	7.0	-1.1	-1.4	-1.4	-1.4	-1.3
AVG	7.5	-0.1	-0.1	0.0	-0.1	0.2
STD	0.5	0.3	0.3	0.3	0.3	0.5
Open	0	0	0	0	0	0
Tech	MOB	GL	MOB	GL	GL	GL
Equip ID	1125	673	1125	1045	1045	1045
	1219	529	1219	529	529	529



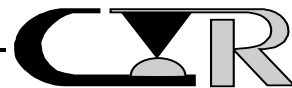
Low Level Contact Resistance						
Project:	206273-2				Spec:	EIA 364, TP23
Customer:	Samtec				Subgroup:	A
Product:	SFM-125-02-S-D-A/TFM-125-02-S-D-A				File #:	206273-259
Description:	ID# 59					
Open circuit voltage:	20mv				Current:	100ma
			Delta values			
			units: milliohms			
Temp °C	23	23	22	22	22	22
R.H. %	60	56	50	50	51	51
Date:	29Jun06	07Jul06	25Jul06	25Jul06	04Aug06	04Aug06
Pos. ID	Initial	25X	7D MFG	1X	7D MFG	1X
			Unmated		Mated	
1	8.5	0.0	2.6	0.6	1.1	1.5
2	7.3	-0.6	0.2	0.5	0.4	0.7
3	7.4	0.9	6.5	2.2	2.4	4.3
4	7.1	-0.3	0.1	0.1	0.1	0.5
5	7.0	0.0	0.2	0.4	0.4	0.6
6	6.9	-0.1	0.0	0.1	0.1	0.5
7	6.3	0.3	1.8	0.6	0.6	0.5
8	6.5	0.1	0.7	0.8	0.4	0.6
9	6.6	0.0	0.2	0.2	0.2	0.3
10	6.5	0.2	0.7	0.4	0.3	0.8
11	6.6	0.0	0.3	0.3	0.3	0.3
12	6.7	0.0	0.2	0.2	0.2	0.3
13	6.7	0.0	0.8	0.5	0.4	0.4
14	7.1	-0.3	0.7	0.3	0.2	0.2
15	7.0	-0.1	1.2	0.3	0.2	0.5
16	7.0	0.1	0.9	0.3	0.4	1.0
17	7.1	0.0	0.4	0.4	0.4	0.2
18	7.4	-0.2	-0.2	0.1	0.3	-0.1
19	7.1	0.6	0.4	0.5	0.6	0.2
20	6.8	0.4	0.2	0.4	0.4	0.9
21	6.9	0.2	0.0	0.2	0.2	0.3
22	6.9	0.3	0.1	0.4	0.3	0.4
23	6.5	0.4	0.3	0.4	0.9	0.3
24	6.9	0.1	0.4	0.5	0.5	0.6
25	7.4	0.2	0.6	0.3	0.1	0.2
MAX	8.5	0.9	6.5	2.2	2.4	4.3
MIN	6.3	-0.6	-0.2	0.1	0.1	-0.1
AVG	7.0	0.1	0.8	0.4	0.4	0.6
STD	0.4	0.3	1.3	0.4	0.5	0.8
Open	0	0	0	0	0	0
Tech	MOB	GL	MOB	GL	GL	GL
Equip ID	1125	673	1125	1045	1045	1045
	1219	529	1219	529	529	529



Low Level Contact Resistance						
Project:	206273-2				Spec:	EIA 364, TP23
Customer:	Samtec				Subgroup:	A
Product:	SFM-125-02-S-D-A/TFM-125-02-S-D-A				File #:	206273-260
Description:	ID# 60					
Open circuit voltage:	20mv			Current:	100ma	
Delta values units: milliohms						
Temp °C	23	23	22	22	22	22
R.H. %	60	56	50	54	51	51
Date:	29Jun06	07Jul06	25Jul06	26Jul06	04Aug06	04Aug06
Pos. ID	Initial	25X	7D MFG	1X	7D MFG	1X
			Unmated		Mated	
1	7.0	0.1	0.1	0.3	0.3	0.2
2	7.4	-0.2	0.1	0.1	0.1	0.1
3	7.6	0.0	-0.1	0.0	-0.1	0.0
4	7.4	-0.5	0.2	0.2	0.1	0.3
5	7.5	-0.4	-0.2	-0.1	-0.2	-0.1
6	7.4	0.0	-0.1	0.1	0.1	1.6
7	7.5	-0.2	0.1	0.3	0.2	0.9
8	7.5	0.0	0.0	0.2	0.1	0.0
9	7.5	0.0	0.0	0.5	0.3	0.3
10	7.5	-0.1	-0.1	0.2	0.1	0.0
11	7.4	-0.2	-0.1	0.2	0.2	0.1
12	7.3	-0.1	0.0	0.2	0.2	0.1
13	7.3	-0.3	0.1	0.2	0.3	0.0
14	7.5	-0.1	0.0	0.0	0.0	0.0
15	7.6	-0.5	-0.2	-0.1	-0.1	0.0
16	7.3	0.8	0.2	0.3	0.3	0.4
17	7.5	-0.2	0.2	0.4	0.4	0.4
18	7.8	0.2	-0.1	-0.1	0.0	0.0
19	7.8	-0.1	0.3	0.2	0.2	-0.4
20	7.5	-0.3	-0.2	-0.1	0.0	-0.1
21	7.6	-0.2	-0.1	-0.1	-0.1	-0.1
22	7.6	-0.1	-0.2	0.0	-0.1	0.0
23	7.5	0.2	0.1	0.2	0.1	0.0
24	9.7	0.3	0.2	-0.9	-1.0	-1.0
25	8.4	-0.2	0.1	0.1	0.0	0.0
MAX	9.7	0.8	0.3	0.5	0.4	1.6
MIN	7.0	-0.5	-0.2	-0.9	-1.0	-1.0
AVG	7.6	-0.1	0.0	0.1	0.1	0.1
STD	0.5	0.3	0.1	0.3	0.3	0.4
Open	0	0	0	0	0	0
Tech	MOB	GL	MOB	GL	GL	GL
Equip ID	1125	673	1125	1045	1045	1045
	1219	529	1219	529	529	529



Low Level Contact Resistance						
Project:	206273-2				Spec:	EIA 364, TP23
Customer:	Samtec				Subgroup:	A
Product:	SFM-125-02-S-D-A/TFM-125-02-S-D-A				File #:	206273-261
Description:	ID# 61					
Open circuit voltage:	20mv				Current:	100ma
Delta values units: milliohms						
Temp °C	23	23	22	22	22	22
R.H. %	60	54	50	50	51	51
Date:	29Jun06	10Jul06	25Jul06	25Jul06	04Aug06	04Aug06
Pos. ID	Initial	25X	7D MFG	1X	7D MFG	1X
			Unmated		Mated	
1	7.4	-0.8	2.5	0.3	3.2	3.3
2	7.2	-0.6	0.4	0.2	0.6	0.5
3	7.7	-0.8	-0.4	-0.1	0.3	0.4
4	7.2	-0.5	0.3	0.4	0.0	0.2
5	7.3	-0.4	-0.2	-0.1	-0.1	-0.1
6	7.2	-0.2	0.5	0.0	0.3	1.5
7	7.5	-0.2	0.6	0.1	0.3	1.7
8	7.5	0.0	-0.1	0.0	0.0	0.1
9	7.2	-0.6	0.4	-0.1	0.0	0.3
10	7.6	-0.2	0.0	-0.2	-0.2	0.2
11	7.4	-0.5	1.0	0.2	0.9	1.3
12	7.1	0.0	0.5	0.1	0.1	0.5
13	7.3	-0.2	-0.1	-0.1	0.1	0.2
14	7.7	-0.2	0.0	-0.3	-0.3	-0.1
15	7.4	-0.2	0.4	-0.2	-0.2	0.2
16	7.3	0.0	0.5	-0.1	-0.1	0.4
17	7.6	0.1	0.0	-0.1	0.0	0.1
18	7.5	0.0	0.6	0.3	0.8	0.7
19	7.4	-0.4	1.1	2.2	2.8	1.9
20	7.5	-0.6	0.1	0.0	0.2	1.0
21	7.2	0.1	0.1	0.0	0.1	0.4
22	7.2	-0.2	0.2	0.1	0.2	1.2
23	7.3	-0.4	0.2	0.1	0.2	0.1
24	7.1	0.2	0.4	0.4	0.4	0.7
25	7.6	0.1	0.2	0.0	-0.1	0.1
MAX	7.7	0.2	2.5	2.2	3.2	3.3
MIN	7.1	-0.8	-0.4	-0.3	-0.3	-0.1
AVG	7.4	-0.3	0.4	0.1	0.4	0.7
STD	0.2	0.3	0.6	0.5	0.8	0.8
Open	0	0	0	0	0	0
Tech	MOB	GL	MOB	GL	GL	GL
Equip ID	1125	673	1125	1045	1045	1045
	1219	529	1219	529	529	529

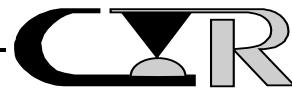


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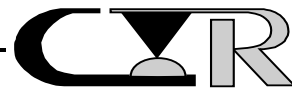
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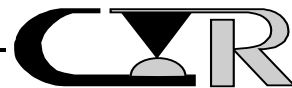
Low Level Contact Resistance						
Project:	206273-2				Spec:	EIA 364, TP23
Customer:	Samtec				Subgroup:	A
Product:	SFM-125-02-S-D-A/TFM-125-02-S-D-A				File #:	206273-262
Description:	ID# 62					
Open circuit voltage:	20mv				Current:	100ma
Delta values units: milliohms						
Temp °C	23	23	22	22	22	22
R.H. %	60	54	50	50	51	51
Date:	29Jun06	10Jul06	25Jul06	25Jul06	04Aug06	04Aug06
Pos. ID	Initial	25X	7D MFG	1X	7D MFG	1X
			Unmated		Mated	
1	8.0	0.0	0.1	0.1	0.1	0.0
2	8.3	-0.8	0.4	-0.1	-0.1	0.1
3	9.0	-0.1	0.2	0.2	0.3	1.1
4	8.2	-0.4	0.1	-0.3	0.0	1.2
5	7.6	-0.4	0.4	-0.2	-0.1	0.5
6	7.9	-0.4	-0.2	-0.1	0.0	-0.1
7	8.0	-0.5	0.5	0.3	0.4	1.7
8	8.0	-0.2	-0.1	-0.1	0.1	0.1
9	8.0	0.0	0.2	0.2	0.3	1.3
10	8.1	-0.7	-0.3	-0.1	-0.2	-0.2
11	8.1	-0.7	-0.2	0.0	0.0	0.4
12	7.7	0.1	-0.1	0.0	-0.1	0.1
13	7.7	-0.3	0.5	0.4	0.5	2.3
14	9.2	-1.3	-0.9	-1.3	-1.3	-1.0
15	8.1	0.1	0.3	0.1	0.1	1.6
16	8.8	-1.6	-0.4	-0.7	-0.7	-0.4
17	7.9	-0.2	0.2	0.0	0.1	0.4
18	7.9	0.3	0.3	0.0	0.2	0.3
19	8.3	-0.4	1.3	0.3	1.0	0.8
20	7.6	-0.2	0.6	0.4	0.5	0.4
21	8.8	-0.3	0.4	0.0	0.2	0.1
22	8.1	-0.2	0.0	0.0	-0.1	1.0
23	7.7	0.0	-0.1	0.1	0.0	0.1
24	7.9	0.1	0.7	0.3	0.5	1.2
25	8.1	-0.3	1.9	0.2	0.9	1.4
MAX	9.2	0.3	1.9	0.4	1.0	2.3
MIN	7.6	-1.6	-0.9	-1.3	-1.3	-1.0
AVG	8.1	-0.3	0.2	0.0	0.1	0.6
STD	0.4	0.4	0.5	0.4	0.5	0.8
Open	0	0	0	0	0	0
Tech	MOB	GL	MOB	GL	GL	GL
Equip ID	1125	673	1125	1045	1045	1045
	1219	529	1219	529	529	529



Low Level Contact Resistance						
Project:	206273-2				Spec:	EIA 364, TP23
Customer:	Samtec				Subgroup:	A
Product:	SFM-125-02-S-D-A/TFM-125-02-S-D-A				File #:	206273-263
Description:	ID# 63					
Open circuit voltage:	20mv				Current:	100ma
Delta values units: milliohms						
Temp °C	23	23	22	22	22	22
R.H. %	60	54	50	50	51	51
Date:	29Jun06	10Jul06	25Jul06	25Jul06	04Aug06	04Aug06
Pos. ID	Initial	25X	7D MFG	1X	7D MFG	1X
			Unmated		Mated	
1	6.9	-0.1	0.4	0.2	0.0	0.8
2	7.2	-0.3	1.2	0.5	0.5	1.6
3	6.8	-0.2	1.3	0.4	0.3	0.5
4	6.9	-0.1	-0.1	0.1	-0.2	0.0
5	6.9	-0.2	0.0	0.1	0.1	0.1
6	6.9	-0.2	0.2	0.3	0.1	0.4
7	7.1	-0.4	0.2	0.0	0.0	0.8
8	7.2	-0.5	-0.4	-0.1	-0.1	-0.1
9	7.9	-1.2	-1.1	-1.0	-1.0	-1.1
10	7.2	-0.5	-0.2	-0.1	-0.2	0.7
11	7.4	-0.5	-0.5	-0.3	-0.3	-0.4
12	7.5	-0.8	-0.8	-0.6	-0.7	-0.7
13	7.1	-0.5	-0.2	0.0	-0.2	0.3
14	7.4	-0.4	-0.1	-0.1	-0.1	-0.1
15	7.4	0.0	0.0	0.1	0.2	1.1
16	7.6	-0.5	-0.4	-0.4	-0.3	-0.4
17	7.4	-0.3	-0.1	-0.1	-0.2	0.7
18	7.7	-0.3	-0.5	-0.6	-0.7	-0.5
19	7.3	-0.5	0.1	0.2	0.3	0.5
20	7.1	-0.5	-0.3	-0.2	-0.4	-0.4
21	7.2	-0.4	-0.2	-0.1	-0.2	-0.2
22	7.0	-0.2	0.3	0.3	0.2	0.3
23	7.2	-0.3	-0.1	-0.1	-0.2	0.0
24	7.1	-0.2	0.0	0.0	-0.2	0.0
25	7.0	-0.3	0.3	0.0	0.3	0.0
MAX	7.9	0.0	1.3	0.5	0.5	1.6
MIN	6.8	-1.2	-1.1	-1.0	-1.0	-1.1
AVG	7.2	-0.4	0.0	-0.1	-0.1	0.2
STD	0.3	0.2	0.5	0.3	0.3	0.6
Open	0	0	0	0	0	0
Tech	MOB	GL	MOB	GL	GL	GL
Equip ID	1125	673	1125	1045	1045	1045
	1219	529	1219	529	529	529



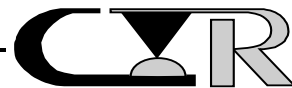
Low Level Contact Resistance						
Project:	206273-2				Spec:	EIA 364, TP23
Customer:	Samtec				Subgroup:	A
Product:	SFM-125-02-S-D-A/TFM-125-02-S-D-A				File #:	206273-264
Description:	ID# 64					
Open circuit voltage:	20mv				Current:	100ma
Delta values units: milliohms						
Temp °C	23	23	22	22	22	22
R.H. %	60	54	50	50	51	51
Date:	29Jun06	10Jul06	25Jul06	25Jul06	04Aug06	04Aug06
Pos. ID	Initial	25X	7D MFG	1X	7D MFG	1X
			Unmated		Mated	
1	7.6	-0.2	-0.1	0.6	0.5	0.6
2	7.2	-0.3	0.2	0.4	0.2	0.3
3	7.7	-0.4	-0.1	0.4	0.3	0.5
4	7.2	0.0	0.0	0.2	0.1	0.1
5	7.5	-0.5	-0.3	0.0	0.0	0.3
6	7.1	-0.1	0.6	0.4	0.2	0.6
7	7.6	-0.2	0.7	0.2	0.0	1.2
8	7.4	-0.2	0.2	0.0	-0.1	0.0
9	7.3	-0.3	0.0	0.2	0.0	0.3
10	7.5	-0.3	-0.1	0.0	0.0	0.1
11	7.6	-0.2	0.0	0.1	-0.1	1.2
12	7.4	-0.5	0.2	0.2	-0.1	0.7
13	7.4	-0.2	0.2	0.0	-0.1	0.0
14	7.8	-0.2	0.4	0.5	0.1	0.8
15	7.4	-0.2	0.5	0.5	0.1	1.5
16	7.6	-0.4	1.8	1.3	0.6	1.6
17	7.5	-0.2	-0.1	0.0	0.0	0.0
18	7.8	-0.5	0.0	0.5	0.0	0.7
19	7.4	-0.2	0.6	0.4	0.3	1.0
20	7.1	0.0	0.5	0.5	0.4	0.6
21	7.1	0.1	0.3	0.4	0.3	0.4
22	7.5	-0.4	0.7	0.2	0.1	0.2
23	7.5	-0.3	-0.1	0.0	0.0	0.2
24	7.6	-0.2	0.0	0.0	-0.1	0.0
25	7.7	-0.3	-0.1	0.0	0.0	0.1
MAX	7.8	0.1	1.8	1.3	0.6	1.6
MIN	7.1	-0.5	-0.3	0.0	-0.1	0.0
AVG	7.5	-0.2	0.2	0.3	0.1	0.5
STD	0.2	0.2	0.4	0.3	0.2	0.5
Open	0	0	0	0	0	0
Tech	MOB	GL	MOB	GL	GL	GL
Equip ID	1125	673	1125	1045	1045	1045
	1219	529	1219	529	529	529



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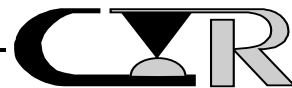
Low Level Contact Resistance						
Project:	206273-2				Spec:	EIA 364, TP23
Customer:	Samtec				Subgroup:	A
Product:	SFM-125-02-S-D-A/TFM-125-02-S-D-A				File #:	206273-265
Description:	ID# 65					
Open circuit voltage:	20mv			Current:	100ma	
Delta values units: milliohms						
Temp °C	23	23	22	22	22	22
R.H. %	60	54	50	50	51	51
Date:	29Jun06	10Jul06	25Jul06	25Jul06	04Aug06	04Aug06
Pos. ID	Initial	25X	7D MFG	1X	7D MFG	1X
			Unmated		Mated	
1	7.1	-0.3	0.4	0.2	0.3	0.2
2	7.0	0.0	0.4	0.2	0.3	0.4
3	7.3	-0.1	0.4	0.7	0.5	1.5
4	7.4	-0.6	0.2	0.3	0.2	0.5
5	7.2	-0.1	0.1	0.3	0.3	0.3
6	7.5	0.0	-0.1	0.0	0.0	0.1
7	7.6	-0.3	0.0	0.2	0.2	1.0
8	7.4	-0.7	0.4	0.2	0.6	0.4
9	7.4	0.0	0.1	0.2	0.2	0.6
10	7.2	0.0	0.0	0.4	0.2	1.5
11	7.5	-0.2	0.0	0.2	0.0	0.7
12	7.5	-0.2	0.0	0.2	0.2	1.5
13	7.9	-0.3	-0.3	-0.1	-0.3	-0.2
14	8.0	-0.5	-0.3	-0.3	-0.4	1.4
15	7.6	-0.1	0.1	0.2	0.1	0.8
16	7.8	-0.2	-0.2	-0.1	-0.1	-0.1
17	7.5	0.0	0.0	0.1	0.2	0.2
18	7.6	-0.5	0.0	0.0	0.1	0.0
19	8.8	-1.7	-0.2	-0.1	0.0	0.0
20	7.3	-0.1	0.0	0.2	0.2	0.2
21	7.3	-0.1	0.0	0.1	0.1	0.5
22	7.3	-0.1	0.1	0.2	0.3	0.4
23	7.3	0.3	0.1	0.2	0.4	0.3
24	7.6	0.2	0.1	0.2	0.4	0.1
25	7.9	-0.1	0.3	0.2	0.1	0.3
MAX	8.8	0.3	0.4	0.7	0.6	1.5
MIN	7.0	-1.7	-0.3	-0.3	-0.4	-0.2
AVG	7.5	-0.2	0.1	0.2	0.2	0.5
STD	0.4	0.4	0.2	0.2	0.2	0.5
Open	0	0	0	0	0	0
Tech	MOB	GL	MOB	GL	GL	GL
Equip ID	1125	673	1125	1045	1045	1045
	1219	529	1219	529	529	529



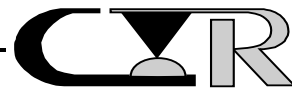
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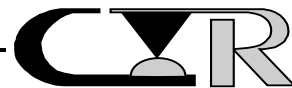
Low Level Contact Resistance						
Project:	206273-2				Spec:	EIA 364, TP23
Customer:	Samtec				Subgroup:	A
Product:	SFM-125-02-S-D-A/TFM-125-02-S-D-A				File #:	206273-266
Description:	ID# 66					
Open circuit voltage:	20mv				Current:	100ma
Delta values units: milliohms						
Temp °C	23	23	22	22	22	22
R.H. %	60	54	50	50	51	51
Date:	29Jun06	10Jul06	25Jul06	25Jul06	04Aug06	04Aug06
Pos. ID	Initial	25X	7D MFG	1X	7D MFG	1X
			Unmated		Mated	
1	7.0	0.0	0.0	0.3	0.0	0.4
2	6.7	-0.3	0.0	0.1	0.1	0.5
3	7.0	-0.4	0.4	0.7	0.7	2.1
4	6.9	-0.4	-0.1	0.1	-0.1	0.8
5	6.9	0.0	-0.2	0.1	0.2	0.8
6	6.9	-0.3	-0.2	-0.1	0.0	0.0
7	7.1	-0.4	-0.1	0.2	0.2	1.6
8	6.6	-0.3	0.0	0.4	0.3	0.8
9	6.8	0.0	0.1	0.3	0.3	0.6
10	7.1	-0.5	-0.3	0.0	-0.1	0.5
11	6.8	-0.1	0.0	0.1	0.0	0.2
12	7.5	-0.6	-0.7	-0.4	-0.5	-0.1
13	7.1	-0.1	-0.3	0.0	-0.1	0.1
14	7.1	-0.2	0.2	0.3	0.1	0.5
15	7.0	-0.2	-0.1	0.0	-0.1	0.2
16	7.2	-0.1	-0.1	-0.1	-0.1	0.1
17	7.1	-0.2	-0.3	-0.1	-0.2	0.3
18	7.0	-0.1	0.1	0.1	0.0	2.4
19	7.2	-0.5	-0.2	-0.1	-0.1	0.0
20	6.9	-0.2	-0.4	0.2	0.1	0.8
21	6.8	-0.2	-0.1	0.0	0.0	0.3
22	7.1	-0.2	-0.2	-0.1	-0.1	0.5
23	6.9	-0.3	0.0	0.0	0.1	0.2
24	7.0	-0.1	0.0	0.0	0.0	0.1
25	7.1	-0.2	0.2	0.2	0.2	0.3
MAX	7.5	0.0	0.4	0.7	0.7	2.4
MIN	6.6	-0.6	-0.7	-0.4	-0.5	-0.1
AVG	7.0	-0.2	-0.1	0.1	0.0	0.6
STD	0.2	0.2	0.2	0.2	0.2	0.6
Open	0	0	0	0	0	0
Tech	MOB	GL	MOB	GL	GL	GL
Equip ID	1125	673	1125	1045	1045	1045
	1219	529	1219	529	529	529



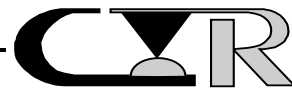
Low Level Contact Resistance						
Project:	206273-2				Spec:	EIA 364, TP23
Customer:	Samtec				Subgroup:	A
Product:	SFM-125-02-S-D-A/TFM-125-02-S-D-A				File #:	206273-267
Description:	ID# 67					
Open circuit voltage:	20mv				Current:	100ma
Delta values units: milliohms						
Temp °C	23	23	22	22	22	22
R.H. %	60	54	50	54	51	51
Date:	29Jun06	10Jul06	25Jul06	26Jul06	04Aug06	04Aug06
Pos. ID	Initial	25X	7D MFG	1X	7D MFG	1X
			Unmated		Mated	
1	7.3	-0.1	0.0	0.1	0.2	0.3
2	7.8	-0.8	-0.4	-0.4	-0.3	0.1
3	7.3	-0.5	0.7	0.6	0.2	0.2
4	7.3	-0.7	-0.6	-0.4	-0.2	-0.2
5	6.9	-0.1	-0.1	0.1	0.2	0.1
6	7.5	-0.2	-0.1	-0.4	-0.4	-0.3
7	7.4	-0.3	0.4	0.5	0.1	0.3
8	7.7	-0.4	-0.6	-0.4	-0.4	-0.4
9	7.5	-0.2	-0.4	-0.3	-0.1	0.1
10	7.5	-0.4	-0.2	-0.2	-0.1	0.2
11	7.4	-0.5	-0.1	0.3	-0.1	-0.1
12	7.6	-0.5	-0.5	-0.3	-0.4	-0.1
13	7.5	-0.6	-0.5	-0.2	0.0	-0.2
14	7.3	-0.6	0.2	0.1	0.0	0.3
15	7.5	-0.2	0.3	0.1	0.1	0.2
16	7.8	-0.6	-0.5	-0.3	-0.4	-0.5
17	8.1	-1.2	-0.8	-0.9	-0.7	-0.8
18	7.4	-0.2	-0.2	-0.1	0.1	-0.1
19	7.6	-1.1	-0.2	0.0	0.2	-0.1
20	7.1	-0.4	0.2	0.0	0.1	0.1
21	7.2	-0.4	-0.1	-0.1	0.0	0.0
22	7.4	-0.4	-0.3	-0.2	0.1	0.1
23	7.2	-0.2	0.0	0.1	0.2	0.1
24	7.4	-0.2	0.1	0.0	0.1	0.1
25	7.5	-0.4	0.4	0.2	0.3	0.2
MAX	8.1	-0.1	0.7	0.6	0.3	0.3
MIN	6.9	-1.2	-0.8	-0.9	-0.7	-0.8
AVG	7.4	-0.4	-0.1	-0.1	0.0	0.0
STD	0.3	0.3	0.4	0.3	0.3	0.3
Open	0	0	0	0	0	0
Tech	MOB	GL	MOB	GL	GL	S.Rath
Equip ID	1125	673	1125	1045	1045	244
	1219	529	1219	529	529	1032



Low Level Contact Resistance						
Project:	206273-2				Spec:	EIA 364, TP23
Customer:	Samtec				Subgroup:	A
Product:	SFM-125-02-S-D-A/TFM-125-02-S-D-A				File #:	206273-268
Description:	ID# 68					
Open circuit voltage:	20mv				Current:	100ma
Delta values units: milliohms						
Temp °C	23	23	22	22	22	22
R.H. %	60	54	50	54	51	51
Date:	29Jun06	10Jul06	25Jul06	26Jul06	04Aug06	04Aug06
Pos. ID	Initial	25X	7D MFG	1X	7D MFG	1X
			Unmated		Mated	
1	7.2	-0.1	0.1	0.0	0.1	0.1
2	7.3	-0.7	0.0	-0.5	-0.3	0.0
3	7.0	-0.3	0.1	-0.2	-0.1	-0.1
4	7.2	-0.6	-0.1	-0.3	-0.3	0.0
5	7.1	-0.1	0.2	-0.1	-0.1	0.1
6	7.1	-0.1	0.0	-0.4	-0.3	0.0
7	6.9	0.1	1.4	0.1	0.6	2.6
8	7.2	-0.4	0.2	-0.2	-0.1	1.6
9	7.1	-0.3	0.1	-0.3	-0.3	1.3
10	7.1	0.3	0.2	-0.4	-0.3	0.7
11	7.0	-0.3	1.8	0.5	0.6	1.8
12	7.3	-0.4	0.8	-0.2	-0.1	1.9
13	7.0	-0.1	0.9	0.1	0.2	1.3
14	7.3	-0.1	1.1	0.4	0.5	1.6
15	7.2	0.0	1.0	0.2	0.2	1.3
16	7.1	0.0	0.5	-0.2	-0.2	0.4
17	7.5	-0.2	0.2	-0.1	-0.1	0.2
18	7.3	0.1	2.3	0.2	0.3	1.1
19	7.3	-0.2	0.3	-0.1	0.0	2.4
20	7.3	-0.4	-0.1	-0.3	-0.2	-0.1
21	6.9	0.1	0.4	0.0	0.0	0.3
22	7.1	-0.4	-0.1	-0.2	-0.2	0.2
23	7.4	-0.3	0.1	-0.1	-0.1	0.1
24	7.5	-0.1	0.1	-0.2	0.1	0.0
25	7.7	-0.1	0.2	0.0	0.0	0.1
MAX	7.7	0.3	2.3	0.5	0.6	2.6
MIN	6.9	-0.7	-0.1	-0.5	-0.3	-0.1
AVG	7.2	-0.2	0.5	-0.1	0.0	0.8
STD	0.2	0.2	0.6	0.2	0.3	0.9
Open	0	0	0	0	0	0
Tech	MOB	GL	MOB	GL	GL	S.Rath
Equip ID	1125	673	1125	1045	1045	244
	1219	529	1219	529	529	1032

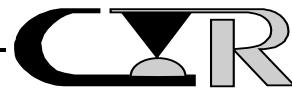


Low Level Contact Resistance						
Project:	206273-2				Spec:	EIA 364, TP23
Customer:	Samtec				Subgroup:	A
Product:	SFM-125-02-S-D-A/TFM-125-02-S-D-A				File #:	206273-269
Description:	ID# 69					
Open circuit voltage:	20mv				Current:	100ma
Delta values units: milliohms						
Temp °C	23	23	22	22	22	22
R.H. %	60	54	50	50	51	52
Date:	29Jun06	10Jul06	25Jul06	25Jul06	04Aug06	07Aug06
Pos. ID	Initial	25X	7D MFG	1X	7D MFG	1X
			Unmated		Mated	
1	6.5	0.1	0.0	0.1	0.0	1.4
2	6.6	0.0	0.1	0.2	0.1	0.9
3	6.3	0.7	0.2	0.3	0.3	0.5
4	6.5	-0.1	0.0	0.2	0.2	0.2
5	6.3	0.7	0.3	0.3	0.3	0.9
6	6.7	0.7	-0.5	-0.2	-0.2	-0.1
7	6.6	0.8	0.0	0.5	0.4	1.0
8	6.6	1.1	0.3	0.4	0.3	0.3
9	6.4	0.0	0.3	1.9	1.1	1.0
10	6.7	0.4	0.6	1.0	0.7	1.5
11	6.5	-0.2	0.3	0.4	0.2	0.6
12	7.0	-0.1	-0.1	-0.1	-0.2	0.6
13	6.7	0.7	-0.1	0.1	0.1	0.9
14	6.9	0.1	0.2	0.3	0.1	1.2
15	7.0	0.5	0.6	0.5	0.3	2.7
16	7.2	-0.1	0.5	0.1	0.1	1.6
17	7.1	-0.4	0.0	0.1	0.0	2.4
18	7.3	0.1	0.8	1.0	0.9	1.7
19	7.1	-0.3	0.5	0.4	0.4	0.1
20	6.2	0.7	0.6	0.6	0.5	0.8
21	7.0	-0.5	-0.5	-0.4	-0.3	0.0
22	6.9	-0.2	0.1	0.2	0.1	0.2
23	6.8	0.1	0.1	0.1	0.1	0.2
24	6.9	0.6	0.7	0.2	0.2	1.7
25	6.9	0.0	0.2	0.1	0.1	0.2
MAX	7.3	1.1	0.8	1.9	1.1	2.7
MIN	6.2	-0.5	-0.5	-0.4	-0.3	-0.1
AVG	6.7	0.2	0.2	0.3	0.2	0.9
STD	0.3	0.4	0.3	0.4	0.3	0.7
Open	0	0	0	0	0	0
Tech	MOB	GL	MOB	GL	GL	S.Rath
Equip ID	1125	673	1125	1045	1045	244
	1219	529	1219	529	529	1032





Low Level Contact Resistance						
Project:	206273-2				Spec:	EIA 364, TP23
Customer:	Samtec				Subgroup:	A
Product:	SFM-125-02-S-D-A/TFM-125-02-S-D-A				File #:	206273-270
Description:	ID# 70					
Open circuit voltage:	20mv			Current:	100ma	
Delta values units: milliohms						
Temp °C	23	23	22	22	22	22
R.H. %	60	54	50	54	51	52
Date:	29Jun06	10Jul06	25Jul06	26Jul06	04Aug06	07Aug06
Pos. ID	Initial	25X	7D MFG	1X	7D MFG	1X
			Unmated		Mated	
1	6.8	0.1	0.2	-0.2	-0.1	0.2
2	6.8	-0.2	0.5	0.1	0.1	0.6
3	7.0	-0.2	1.0	0.2	0.2	0.6
4	6.9	0.1	0.0	0.2	0.1	0.2
5	6.9	0.0	0.3	0.0	0.0	0.1
6	6.9	-0.3	0.0	0.0	-0.1	0.0
7	7.1	0.3	0.1	0.1	0.1	0.1
8	7.0	0.3	0.2	0.0	-0.1	0.2
9	7.0	-0.2	-0.1	-0.1	-0.1	0.0
10	7.2	-0.4	0.0	-0.4	-0.5	0.0
11	7.1	-0.4	-0.1	-0.1	-0.3	0.0
12	7.1	-0.3	-0.1	-0.2	-0.3	0.0
13	7.5	-0.5	-0.4	-0.7	-0.6	-0.4
14	7.3	-0.2	0.2	0.0	-0.1	1.0
15	7.8	-0.6	-0.5	-0.5	-0.6	-0.3
16	7.5	-0.3	0.1	-0.4	-0.5	1.6
17	7.3	-0.2	0.4	0.0	-0.3	0.7
18	7.5	-0.1	0.6	0.3	0.1	0.7
19	7.4	-0.2	0.4	0.3	-0.7	1.5
20	6.8	-0.3	0.1	0.0	0.0	0.3
21	7.0	-0.2	-0.1	-0.1	-0.2	0.0
22	7.1	-0.1	0.0	-0.2	0.0	0.0
23	7.1	0.0	0.0	0.0	-0.1	0.0
24	7.1	0.0	0.3	0.4	0.4	0.4
25	7.3	-0.1	0.3	0.2	0.0	0.6
MAX	7.8	0.3	1.0	0.4	0.4	1.6
MIN	6.8	-0.6	-0.5	-0.7	-0.7	-0.4
AVG	7.1	-0.2	0.1	0.0	-0.1	0.3
STD	0.3	0.2	0.3	0.3	0.3	0.5
Open	0	0	0	0	0	0
Tech	MOB	GL	GL	GL	GL	S.Rath
Equip ID	1125	673	1045	1045	1045	244
	1219	529	529	529	529	1032



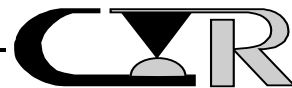
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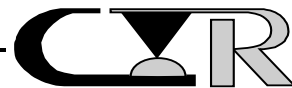
Low Level Contact Resistance						
Project:	206273-2				Spec:	EIA 364, TP23
Customer:	Samtec				Subgroup:	A
Product:	SFM-125-02-S-D-A/TFM-125-02-S-D-A				File #:	206273-271
Description:	ID# 71					
Open circuit voltage:	20mv				Current:	100ma
			Delta values			
			units: milliohms			
Temp °C	23	23	22	22	22	22
R.H. %	60	54	50	54	51	52
Date:	29Jun06	10Jul06	25Jul06	26Jul06	04Aug06	07Aug06
Pos. ID	Initial	25X	7D MFG	1X	7D MFG	1X
			Unmated		Mated	
1	7.2	0.0	0.0	0.3	0.2	1.3
2	8.0	-0.7	-0.6	-0.6	-0.5	0.5
3	7.6	-0.3	1.0	0.3	-0.1	1.4
4	7.3	-0.5	-0.1	-0.3	-0.4	-0.5
5	7.4	-0.2	-0.2	0.0	-0.2	0.4
6	7.0	0.1	0.1	0.3	0.2	0.7
7	8.2	-0.4	-0.7	-0.4	-0.5	0.0
8	8.1	-0.5	-0.3	-0.5	-0.6	0.9
9	7.3	-0.2	0.1	0.0	0.1	0.6
10	7.3	-0.1	0.1	0.5	0.3	0.5
11	7.4	0.0	-0.2	0.0	-0.1	0.2
12	7.6	-0.4	-0.5	-0.3	-0.5	-0.3
13	8.0	-0.8	-0.4	-0.6	-0.7	-0.6
14	7.5	-0.1	-0.2	0.0	-0.1	0.2
15	7.4	-0.3	-0.1	0.1	-0.2	0.2
16	7.7	-0.3	-0.2	-0.2	-0.3	-0.2
17	8.1	-1.3	-0.6	-0.9	-0.8	-0.7
18	7.4	-0.4	0.0	0.0	-0.1	0.2
19	8.0	-0.5	-0.3	-0.2	-1.0	-0.1
20	7.0	-0.3	0.0	-0.1	0.2	0.2
21	7.1	0.1	0.1	0.1	0.1	0.0
22	7.3	-0.3	-0.1	0.0	0.1	0.2
23	7.2	-0.1	-0.1	0.1	0.0	0.2
24	7.2	0.1	0.2	0.2	0.3	0.4
25	7.4	0.2	0.0	0.5	0.4	0.6
MAX	8.2	0.2	1.0	0.5	0.4	1.4
MIN	7.0	-1.3	-0.7	-0.9	-1.0	-0.7
AVG	7.5	-0.3	-0.1	-0.1	-0.2	0.3
STD	0.4	0.3	0.3	0.3	0.4	0.5
Open	0	0	0	0	0	0
Tech	MOB	GL	GL	GL	GL	S.Rath
Equip ID	1125	673	1045	1045	1045	244
	1219	529	529	529	529	1032



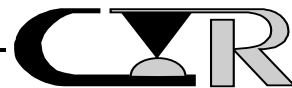
Low Level Contact Resistance						
Project:	206273-2				Spec:	EIA 364, TP23
Customer:	Samtec				Subgroup:	A
Product:	SFM-125-02-S-D-A/TFM-125-02-S-D-A				File #:	206273-272
Description:	ID# 72					
Open circuit voltage:	20mv			Current:	100ma	
Delta values units: milliohms						
Temp °C	23	23	22	22	22	22
R.H. %	60	54	50	54	51	52
Date:	29Jun06	10Jul06	25Jul06	26Jul06	04Aug06	07Aug06
Pos. ID	Initial	25X	7D MFG	1X	7D MFG	1X
			Unmated		Mated	
1	7.3	-0.7	0.0	0.0	0.3	0.9
2	7.4	-0.2	-0.3	-0.2	-0.1	0.0
3	7.5	-0.2	-0.1	-0.2	-0.1	0.1
4	7.2	0.0	1.0	0.6	1.1	1.7
5	7.7	-0.4	-0.3	-0.3	-0.4	0.0
6	6.9	-0.1	0.4	0.4	0.4	0.5
7	7.6	-0.1	0.2	0.4	0.4	0.2
8	7.2	-0.1	0.3	0.4	1.0	1.6
9	7.2	0.0	0.0	0.0	-0.2	0.4
10	7.4	-0.2	-0.1	-0.1	-0.2	0.1
11	7.3	-0.2	-0.3	-0.2	-0.2	0.1
12	7.2	-0.1	0.1	0.2	0.2	0.3
13	7.3	-0.4	-0.1	0.0	0.0	0.6
14	7.3	-0.5	-0.2	-0.1	-0.2	0.0
15	7.7	-0.6	-0.4	-0.2	-0.3	-0.1
16	7.6	-0.4	-0.1	-0.1	0.0	0.1
17	8.4	-1.0	-0.9	-0.8	-0.9	-0.6
18	7.5	-0.1	0.8	0.4	0.3	0.2
19	7.4	-0.2	0.2	0.5	0.6	2.5
20	7.3	-0.1	0.0	0.0	0.2	0.9
21	7.3	-0.3	0.0	-0.1	0.0	0.3
22	7.5	-0.2	-0.1	-0.1	0.0	0.1
23	7.7	-0.2	-0.3	-0.2	-0.2	-0.1
24	7.5	-0.6	0.5	0.2	0.5	1.2
25	7.7	-0.3	0.8	0.1	2.1	1.5
MAX	8.4	0.0	1.0	0.6	2.1	2.5
MIN	6.9	-1.0	-0.9	-0.8	-0.9	-0.6
AVG	7.4	-0.3	0.0	0.0	0.2	0.5
STD	0.3	0.2	0.4	0.3	0.6	0.7
Open	0	0	0	0	0	0
Tech	MOB	GL	GL	GL	GL	S.Rath
Equip ID	1125	673	1045	1045	1045	244
	1219	529	529	529	529	1032



Low Level Contact Resistance						
Project:	206273-2				Spec:	EIA 364, TP23
Customer:	Samtec				Subgroup:	A
Product:	SFM-125-02-S-D-A/TFM-125-02-S-D-A				File #:	206273-273
Description:	ID# 73					
Open circuit voltage:	20mv				Current:	100ma
Delta values units: milliohms						
Temp °C	23	23	22	22	22	22
R.H. %	60	54	50	54	51	52
Date:	29Jun06	10Jul06	25Jul06	26Jul06	04Aug06	07Aug06
Pos. ID	Initial	25X	MFG	1X	7D MFG	1X
			Unmated		Mated	
1	8.0	1.2	2.3	1.5	3.8	4.5
2	8.2	1.3	1.9	0.8	2.0	2.1
3	7.8	0.5	1.0	0.5	1.2	0.7
4	7.3	1.7	4.5	3.4	3.9	5.2
5	7.5	2.0	2.4	2.1	2.2	1.1
6	7.9	1.0	1.8	1.6	1.1	1.5
7	7.2	-0.1	0.0	-0.1	0.0	0.0
8	8.4	0.5	1.0	0.6	0.9	0.3
9	7.7	0.3	1.1	0.9	-0.1	0.6
10	7.7	0.3	1.1	0.7	0.9	0.5
11	8.1	0.5	-0.4	-0.4	0.1	-0.4
12	7.0	0.5	1.1	1.2	1.9	0.9
13	7.1	0.7	1.2	1.1	1.3	1.4
14	7.8	0.4	0.7	0.5	0.0	0.1
15	7.9	0.6	1.3	1.3	0.9	0.7
16	7.6	-0.5	-0.3	-0.3	-0.3	-0.3
17	7.3	-0.2	0.0	0.1	-0.1	-0.1
18	7.2	-0.1	0.1	0.0	0.0	-0.1
19	7.4	-0.4	0.1	-0.1	0.2	0.1
20	8.3	0.6	1.3	1.4	1.2	1.4
21	7.9	1.4	1.8	1.5	1.8	1.7
22	8.0	0.1	0.8	0.2	0.6	1.2
23	8.3	1.3	1.5	1.2	1.0	1.2
24	7.3	-0.3	0.0	0.0	0.0	0.5
25	8.5	-0.8	-0.3	-0.4	-0.4	0.8
MAX	8.5	2.0	4.5	3.4	3.9	5.2
MIN	7.0	-0.8	-0.4	-0.4	-0.4	-0.4
AVG	7.7	0.5	1.0	0.8	1.0	1.0
STD	0.4	0.7	1.1	0.9	1.1	1.3
Open	0	0	0	0	0	0
Tech	MOB	GL	GL	GL	GL	S.Rath
Equip ID	1125	673	1045	1045	1045	244
	1219	529	529	529	529	1032



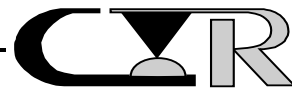
Low Level Contact Resistance						
Project:	206273-2				Spec:	EIA 364, TP23
Customer:	Samtec				Subgroup:	A
Product:	SFM-125-02-S-D-A/TFM-125-02-S-D-A				File #:	206273-274
Description:	ID# 74					
Open circuit voltage:	20mv				Current:	100ma
Delta values units: milliohms						
Temp °C	23	23	22	22	22	22
R.H. %	60	54	50	54	51	52
Date:	29Jun06	10Jul06	25Jul06	26Jul06	04Aug06	07Aug06
Pos. ID	Initial	25X	7D MFG	1X	7D MFG	1X
			Unmated		Mated	
1	7.4	-0.2	0.7	0.0	0.2	-0.1
2	6.8	-0.2	0.3	0.1	0.0	0.2
3	7.0	-0.1	0.1	-0.3	0.0	-0.1
4	6.9	0.0	0.3	0.2	0.1	0.6
5	6.9	-0.3	0.2	0.3	0.2	0.7
6	6.8	0.1	0.2	-0.1	0.1	0.6
7	7.7	-0.4	0.3	-0.2	-0.1	1.0
8	7.4	-0.3	0.8	-0.2	-0.2	0.7
9	8.1	-1.1	-0.6	-0.8	-0.7	-0.4
10	6.9	-0.2	1.8	0.2	0.1	2.3
11	6.9	-0.2	1.0	0.7	0.8	2.1
12	7.2	-0.2	0.8	-0.1	0.0	2.9
13	6.9	-0.3	0.1	0.2	0.0	0.5
14	7.2	-0.3	-0.1	-0.1	-0.3	0.3
15	7.4	-0.3	-0.3	-0.4	-0.4	-0.1
16	7.9	-0.6	-0.9	-1.1	-1.2	-0.8
17	7.2	0.0	0.1	0.0	-0.1	0.9
18	7.3	-0.1	1.4	1.4	1.1	0.4
19	7.6	-0.3	0.0	0.0	0.1	-0.1
20	6.9	0.0	0.4	0.1	0.2	1.0
21	6.8	-0.1	0.6	0.3	0.2	0.5
22	6.8	0.1	0.0	0.0	0.0	0.4
23	7.1	0.1	0.1	0.0	0.0	0.6
24	7.1	0.1	0.0	-0.1	-0.1	0.6
25	7.2	0.0	0.1	0.1	0.1	0.5
MAX	8.1	0.1	1.8	1.4	1.1	2.9
MIN	6.8	-1.1	-0.9	-1.1	-1.2	-0.8
AVG	7.2	-0.2	0.3	0.0	0.0	0.6
STD	0.4	0.3	0.6	0.5	0.4	0.8
Open	0	0	0	0	0	0
Tech	MOB	GL	GL	GL	GL	S.Rath
Equip ID	1125	673	1045	1045	1045	244
	1219	529	529	529	529	1032



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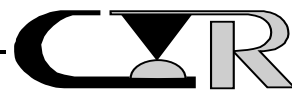
Low Level Contact Resistance						
Project:	206273-2				Spec:	EIA 364, TP23
Customer:	Samtec				Subgroup:	A
Product:	SFM-125-02-S-D-A/TFM-125-02-S-D-A				File #:	206273-275
Description:	ID# 75					
Open circuit voltage:	20mv			Current:	100ma	
Delta values units: milliohms						
Temp °C	23	23	22	22	22	22
R.H. %	60	54	50	54	51	52
Date:	29Jun06	10Jul06	25Jul06	26Jul06	04Aug06	07Aug06
Pos. ID	Initial	25X	7D MFG	1X	7D MFG	1X
			Unmated		Mated	
1	6.9	0.0	0.1	0.3	0.5	2.9
2	7.5	0.1	0.1	0.2	0.1	0.3
3	7.5	0.0	-0.1	0.0	0.0	0.2
4	7.4	0.1	1.9	0.2	0.2	0.8
5	7.3	-0.1	-0.1	-0.2	-0.1	0.0
6	7.6	0.2	0.3	0.0	-0.1	0.1
7	7.3	-0.1	0.3	0.3	0.7	2.9
8	7.1	-0.2	0.1	0.3	0.3	0.5
9	7.1	0.1	1.4	0.6	0.7	3.4
10	7.3	0.0	0.2	0.1	0.2	0.4
11	7.4	0.0	0.1	0.1	0.1	0.0
12	7.4	-0.2	0.0	0.0	0.1	0.1
13	7.4	0.1	0.1	0.1	0.1	0.1
14	7.6	-0.1	0.0	-0.2	-0.3	-0.2
15	7.9	-0.4	0.4	0.0	-0.2	-0.1
16	7.8	-0.2	0.3	0.0	-0.2	0.0
17	7.7	-0.3	0.0	0.0	-0.2	0.0
18	8.3	-0.3	-0.3	-0.6	-0.3	-0.4
19	9.0	0.0	0.4	-0.1	0.0	0.0
20	7.4	0.1	0.0	0.1	0.0	0.0
21	7.7	-0.3	-0.3	0.0	0.0	0.1
22	7.7	0.1	-0.1	0.1	0.1	0.1
23	7.9	-0.3	-0.3	-0.1	-0.2	-0.1
24	8.0	0.0	0.1	0.1	0.0	0.2
25	7.9	-0.1	0.3	0.1	0.1	0.3
MAX	9.0	0.2	1.9	0.6	0.7	3.4
MIN	6.9	-0.4	-0.3	-0.6	-0.3	-0.4
AVG	7.6	-0.1	0.2	0.1	0.1	0.5
STD	0.4	0.2	0.5	0.2	0.3	1.0
Open	0	0	0	0	0	0
Tech	MOB	GL	GL	GL	GL	S.Rath
Equip ID	1125	673	1045	1045	1045	244
	1219	529	529	529	529	1032



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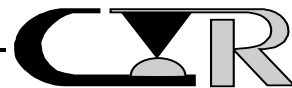
Low Level Contact Resistance						
Project:	206273-2				Spec:	EIA 364, TP23
Customer:	Samtec				Subgroup:	A
Product:	SFM-125-02-S-D-A/TFM-125-02-S-D-A				File #:	206273-276
Description:	ID# 76					
Open circuit voltage:	20mv			Current:	100ma	
Delta values units: milliohms						
Temp °C	22	22	22	22	22	22
R.H. %	56	56	50	54	51	52
Date:	12Jul06	12Jul06	25Jul06	26Jul06	04Aug06	07Aug06
Pos. ID	Initial	25X	7D MFG	1X	7D MFG	1X
			Unmated		Mated	
1	7.7	-0.4	-0.2	0.1	0.0	0.0
2	7.4	-0.2	-0.2	-0.1	-0.2	0.0
3	7.7	-0.3	-0.1	-0.2	-0.2	2.2
4	7.9	-0.3	-0.6	-0.6	-0.7	-0.2
5	7.9	-0.5	-0.8	-0.6	-0.6	-0.6
6	7.4	0.0	-0.1	0.0	0.1	0.4
7	7.5	0.0	-0.2	-0.1	-0.1	0.2
8	7.8	-0.3	-0.4	-0.3	-0.6	-0.2
9	7.7	0.0	-0.5	-0.2	-0.4	0.0
10	7.4	0.0	-0.1	0.0	-0.3	0.2
11	7.8	-0.3	-0.4	-0.3	-0.5	-0.4
12	7.4	0.0	-0.2	-0.1	-0.5	-0.1
13	7.5	-0.3	-0.6	-0.1	-0.2	-0.1
14	7.2	-0.1	0.0	0.1	0.1	2.4
15	7.0	-0.1	-0.3	0.1	0.3	1.4
16	7.0	0.1	0.1	0.0	-0.1	0.1
17	6.9	-0.1	-0.1	0.1	-0.1	0.1
18	7.0	0.0	-0.1	0.0	-0.2	0.4
19	6.9	0.0	-0.1	0.3	0.3	0.7
20	7.6	-0.4	-0.4	-0.4	-0.6	0.1
21	6.6	0.4	0.6	0.4	0.3	2.6
22	7.4	-0.2	-0.2	-0.1	0.0	0.9
23	7.2	-0.3	0.0	0.0	0.1	0.1
24	6.9	-0.1	0.1	0.3	0.5	0.3
25	6.9	-0.1	2.3	2.1	2.0	2.6
MAX	7.9	0.4	2.3	2.1	2.0	2.6
MIN	6.6	-0.5	-0.8	-0.6	-0.7	-0.6
AVG	7.3	-0.1	-0.1	0.0	-0.1	0.5
STD	0.4	0.2	0.6	0.5	0.5	0.9
Open	0	0	0	0	0	0
Tech	MOB	MOB	MOB	GL	GL	S.Rath
Equip ID	1125	1125	1125	1045	1045	244
	1219	1219	1219	529	529	1032



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Low Level Contact Resistance						
Project:	206273-2				Spec:	EIA 364, TP23
Customer:	Samtec				Subgroup:	A
Product:	SFM-125-02-S-D-A/TFM-125-02-S-D-A				File #:	206273-277
Description:	ID# 77					
Open circuit voltage:	20mv				Current:	100ma
Delta values units: milliohms						
Temp °C	22	22	22	22	22	22
R.H. %	56	56	50	54	51	52
Date:	12Jul06	12Jul06	25Jul06	26Jul06	04Aug06	07Aug06
Pos. ID	Initial	25X	MFG 7d	1X	MFG 7d	1X
			Unmated		Mated	
1	6.8	0.1	0.4	0.4	0.7	0.4
2	7.2	-0.1	0.1	0.2	0.2	-0.1
3	7.1	-0.1	0.1	0.2	0.2	0.2
4	7.6	-0.5	-0.4	-0.3	-0.3	-0.4
5	8.4	-0.8	-1.0	-0.6	-0.9	-0.4
6	7.4	-0.4	-0.3	-0.1	-0.1	-0.3
7	6.9	-0.2	0.0	0.0	0.1	0.1
8	6.9	-0.1	0.0	0.1	0.0	0.0
9	7.2	-0.2	-0.3	-0.2	-0.1	0.0
10	7.4	-0.2	-0.3	-0.2	-0.1	-0.3
11	7.1	0.0	0.1	-0.1	-0.2	-0.3
12	7.4	-0.4	-0.3	-0.3	-0.2	-0.1
13	7.0	-0.3	-0.1	0.1	0.0	0.1
14	6.8	-0.1	0.0	0.1	0.2	0.0
15	7.3	-0.2	-0.2	-0.2	-0.2	3.1
16	7.2	-0.3	-0.1	-0.1	-0.1	-0.1
17	7.4	-0.4	0.0	-0.2	-0.2	-0.1
18	7.4	-0.2	-0.1	0.0	-0.1	0.0
19	7.0	-0.3	-0.1	0.0	0.0	-0.1
20	7.8	-0.3	-0.5	-0.4	-0.5	-0.5
21	7.5	-0.5	-0.2	-0.1	0.0	-0.2
22	7.1	0.2	0.1	0.3	0.3	-0.1
23	7.3	-0.3	0.1	0.3	0.3	0.0
24	7.3	-0.1	0.3	0.2	0.1	-0.1
25	7.5	-0.4	0.1	0.0	0.0	0.0
MAX	8.4	0.2	0.4	0.4	0.7	3.1
MIN	6.8	-0.8	-1.0	-0.6	-0.9	-0.5
AVG	7.3	-0.2	-0.1	0.0	0.0	0.0
STD	0.3	0.2	0.3	0.2	0.3	0.7
Open	0	0	0	0	0	0
Tech	MOB	MOB	GL	GL	GL	S.Rath
Equip ID	1125	1125	1045	1045	1045	244
	1219	1219	529	529	529	1032



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# TEST RESULTS

## GROUP 2



PROJECT NO.: 206273-2 SPECIFICATION: CISCO EDCS-164608

PART NO.: See page 4 PART DESCRIPTION: Plug / Receptacle Connector

SAMPLE SIZE: See page 4 TECHNICIAN: MOB

START DATE: 7/13/06 COMPLETE DATE: 7/14/06

ROOM AMBIENT: 22°C RELATIVE HUMIDITY: 54%

EQUIPMENT ID#: 1125, 1219

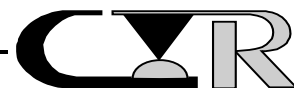
LOW LEVEL CIRCUIT RESISTANCE (LLCR)

PURPOSE:

1. To evaluate contact resistance characteristics of the contact systems under conditions where applied voltages and currents do not alter the physical contact interface and will detect oxides and films which degrade electrical stability. It is also sensitive to and may detect the presence of fretting corrosion induced by mechanical or thermal environments as well as any significant loss of contact pressure.
2. This attribute was monitored after each preconditioning and/or test exposure in order to determine said stability of the contact systems as they progress through the applicable test sequences.
3. The electrical stability of the system is determined by comparing the initial resistance value to that observed after a given test exposure. The difference is the change in resistance occurring whose magnitude establishes the stability of the interface being evaluated.

PROCEDURE:

1. The test was performed in accordance with EIA 364, Test Procedure 23 with the following conditions:
2. Test Conditions:
  - a) Test Current : 100 milliamps maximum
  - b) Open Circuit Voltage : 20 millivolts
  - c) No. of Positions Tested : 25 per test sample



REQUIREMENTS:

Low level circuit resistance shall be measured and recorded.

-----  
RESULTS:

1. The following is a summary of the data observed:

LOW LEVEL CIRCUIT RESISTANCE  
(Milliohms)

<u>SFM/TFM ID#</u>	<u>Avg.</u>	<u>Max.</u>	<u>Min.</u>
78	7.2	8.3	3.0
79	7.2	7.8	6.8
80	7.6	7.9	7.3
81	6.6	7.1	6.1
82	7.4	7.8	7.1
83	7.3	7.8	6.9
84	6.8	7.4	6.4
85	6.6	7.1	6.2

2. See the following data files for individual data points:

-SFM/TFM : 206273-278 through 206273-285



PROJECT NO.: 206273-2                      SPECIFICATION: CISCO EDCS-164608

PART NO.: See page 4                      PART DESCRIPTION: Plug / Receptacle  
Connector

SAMPLE SIZE: See page 4                      TECHNICIAN:      MOB

START DATE:      7/13/06                      COMPLETE DATE:      7/14/06

ROOM AMBIENT:      22°C                      RELATIVE HUMIDITY:      54%

EQUIPMENT ID#:      150, 340, 1125, 1219

DURABILITY

PURPOSE:

1. This is a preconditioning sequence which is used to induce the type of wear on the contacting surfaces which may occur under normal service conditions. The connectors are mated and unmated a predetermined number of cycles. Upon completion, the units being evaluated are exposed to the environments as specified to assess any impact on electrical stability resulting from wear or other wear dependent phenomenon.
2. This type of preconditioning sequence is also used to mechanically stress the connector system as would normally occur in actual service. This sequence in conjunction with other tests is used to determine if a significant loss of contact pressure occurs from said stresses which in turn, may result in an unstable electrical condition to exist.

PROCEDURE:

1. The test was performed in accordance with EIA 364, Test Procedure 09.
2. Test Conditions:
  - a) No. of Cycles                      :      25
  - b) Rate                                      :      1.0 inch per minute
3. The test samples were assembled to special holding devices and attached to the manual cycling equipment.
4. The test samples were axially aligned to accomplish the mating and unmating function allowing for self-centering movement.



PROCEDURE: continued

5. Care was taken to prevent the mating faces of the test samples from contacting each other.
6. All subsequent variable testing was performed in accordance with the procedures previously indicated.

-----  
REQUIREMENTS:

1. There shall be no evidence of physical damage to the test samples so tested.
2. The change in low level circuit resistance shall not exceed +10.0 milliohms.

-----  
RESULTS:

1. There was no evidence of physical damage to the test samples as tested.
2. The following is a summary of the data observed:

CHANGE IN  
LOW LEVEL CIRCUIT RESISTANCE  
(Milliohms)

<u>SFM/TFM ID#</u>	<u>Avg. Change</u>	<u>Max. Change</u>
78	-0.2	+0.1
79	-0.1	+0.2
80	-0.1	+1.2
81	-0.2	+0.2
82	-0.1	+0.0
83	-0.2	+0.2
84	-0.1	+0.1
85	-0.1	+0.2

3. See the following data files for individual data points:

-SFM/TFM : 206273-278 through 206273-285



PROJECT NO.: 206273-2                      SPECIFICATION: CISCO EDCS-164608

PART NO.: See page 4                      PART DESCRIPTION: Plug / Receptacle  
Connector

SAMPLE SIZE: See page 4                      TECHNICIAN:      MOB

START DATE:      7/17/06                      COMPLETE DATE:      8/8/06

ROOM AMBIENT:      22°C                      RELATIVE HUMIDITY:      52%

EQUIPMENT ID#: 102, 208, 215, 543, 569, 579, 586, 673, 1077,  
1219, 1287, 1297, 1298, 1326, 1334

MIXED FLOWING GAS

PURPOSE:

1. To determine the impact on electrical stability of contact interfaces when the test samples are exposed to a mixed flowing gas environment. Said environment is based on field data simulating typical, severe, non-benign environments. Said exposure is indicative of expected behavior in the field.
2. Mixed flowing gas tests (MFG) are environmental test procedures whose primary purpose is to evaluate product performance under simulated storage or operating (field) conditions. For parts involving plated contact surfaces, such tests are also used to measure the effect of plating degradation (due to the environment) on the electrical and durability properties of a contact or connector system. The specific test conditions are usually chosen so as to simulate, in the test laboratory, the effects of certain representative field environments or environmental severity levels on standard metallic surfaces.

PROCEDURE:

1. The test environment was performed in accordance with EIA 364, Test Procedure 65 with the following conditions.



PROCEDURE: continued

2. Environmental Conditions:

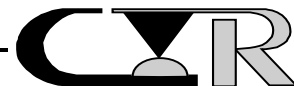
- a) Temperature : 30°C ± 1°C
- b) Relative Humidity : 70% ± 2%
- c) Cl<sub>2</sub> : 10 ± 3 ppb
- d) NO<sub>2</sub> : 200 ± 50 ppb
- e) H<sub>2</sub>S : 10 ± 5 ppb
- f) SO<sub>2</sub> : 100 ± 20 ppb
- g) Exposure Time : 14 days
- h) Mating Conditions : Mated
- i) Mounting Conditions : Mounted

- 3. The test chamber was allowed to stabilize at the specified conditions indicated.
- 4. After stabilization, the test samples and control coupons were placed in the chamber such that they were no closer than 2.0" from each other and/or the chamber walls.
- 5. The test samples were handled in a manner so as not to disturb the contact interface.
- 6. After placement of the test samples in the chamber, it was allowed to re-stabilize and adjusted as required to maintain the specified concentrations and conditions.
- 7. The test chamber was monitored periodically during the exposure period to assure the environmental conditions as specified were maintained.
- 8. Following completion of the 14 day Mixed Flowing Gas exposure, the test samples were subjected to 1 mating cycle.

-----  
REQUIREMENTS:

- 1. There shall be no evidence of damage or corrosion to the test samples as exposed which will cause mechanical or electrical malfunction of the said samples.
- 2. The change in low level circuit resistance shall not exceed +10.0 milliohms.

-----  
RESULTS: See next page



RESULTS: continued

1. There was no evidence of physical damage or corrosion.
2. The following is a summary of the data observed:

MAXIMUM CHANGE IN  
LOW LEVEL CIRCUIT RESISTANCE  
(Milliohms)

<u>SFM/TFM ID#</u>	<u>Day 1-14</u>	
	<u>Mated</u>	<u>1 Cycle</u>
78	+0.8	+0.9
79	+0.3	+0.3
80	+1.4	+1.2
81	+0.5	+0.5
82	+0.5	+0.4
83	+0.7	+0.6
84	+0.3	+0.5
85	+0.4	+0.3

3. See the following data files for individual data points:

-SFM/TFM : 206273-278 through 206273-285

4. Five copper coupons were placed in the chamber. Upon removal said coupons were evaluated via weight gain technique with the following results:

<u>Coupon No.</u>	<u>WEIGHT GAIN (<math>\mu\text{gm}/\text{cm}^2/\text{Day}</math>)</u>	
	<u>Day 1-7</u>	<u>Day 8-10</u>
1	14	12+
2	13	13+
3	13	14
4	15	14
5	12+	14+

Requirement: 12 TO 16  $\mu\text{gm}/\text{cm}^2/\text{Day}$





# LLCR DATA FILES

## FILE NUMBERS

### SFM/TFM

206273-278

206273-279

206273-280

206273-281

206273-282

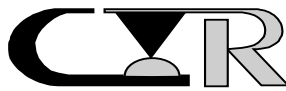
206273-283

206273-284

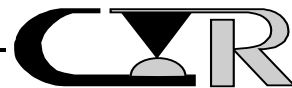
206273-285



Low Level Contact Resistance						
Project:	206273-2				Spec:	EIA 364, TP23
Customer:	Samtec				Subgroup:	B
Product:	SFM-125-02-S-D-A/TFM-125-02-S-D-A				File #:	206273-278
Description:	ID# 78					
Open circuit voltage:	20mv			Current:	100ma	
Delta values units: milliohms						
Temp °C	22	22	22	22		
R.H. %	58	53	52	52		
Date:	13Jul06	14Jul06	07Aug06	07Aug06		
Pos. ID	Initial	25X	14D MFG	1X		
Mated						
1	7.7	-0.3	0.5	0.0		
2	7.6	-0.1	0.3	0.1		
3	7.7	-0.1	-0.2	-0.1		
4	7.9	-0.3	-0.2	-0.1		
5	7.6	0.0	0.0	0.0		
6	7.4	0.0	0.1	0.3		
7	7.3	0.0	0.1	0.2		
8	8.3	-0.9	-0.5	-0.7		
9	7.7	-0.4	-0.3	-0.3		
10	7.7	-0.3	-0.2	-0.1		
11	7.5	-0.1	-0.1	-0.1		
12	7.9	-0.4	-0.4	-0.3		
13	7.6	-0.5	-0.1	0.0		
14	7.4	-0.2	-0.1	-0.1		
15	7.6	-0.2	-0.1	0.0		
16	7.2	-0.2	-0.1	-0.1		
17	7.7	-0.3	-0.2	-0.2		
18	7.4	-0.2	-0.1	-0.3		
19	6.8	0.1	0.2	0.2		
20	7.3	0.0	0.1	0.4		
21	3.4	0.0	-0.7	-0.6		
22	3.0	0.0	0.8	0.7		
23	7.2	0.0	0.3	0.3		
24	7.2	0.0	0.7	0.9		
25	7.3	0.0	0.4	0.2		
MAX	8.3	0.1	0.8	0.9		
MIN	3.0	-0.9	-0.7	-0.7		
AVG	7.2	-0.2	0.0	0.0		
STD	1.2	0.2	0.3	0.3		
Open	0	0	0	0		
Tech	MOB	MOB	MOB	MOB		
Equip ID	1125	1125	673	673		
	1219	1219	1219	1219		
*Pos. 21 and 22 are shorted together						



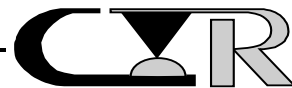
Low Level Contact Resistance						
Project:	206273-2				Spec:	EIA 364, TP23
Customer:	Samtec				Subgroup:	B
Product:	SFM-125-02-S-D-A/TFM-125-02-S-D-A				File #:	206273-279
Description:	ID# 79					
Open circuit voltage:	20mv			Current:	100ma	
Delta values units: milliohms						
Temp °C	22	22	22	22		
R.H. %	58	53	52	52		
Date:	13Jul06	14Jul06	07Aug06	07Aug06		
Pos. ID	Initial	25X	14D MFG	1X		
			Mated			
1	7.0	-0.1	0.2	0.2		
2	7.3	0.1	0.1	0.1		
3	7.2	-0.1	0.0	0.0		
4	7.3	0.0	0.0	0.0		
5	7.2	0.0	0.0	0.0		
6	7.2	0.0	0.2	0.1		
7	7.3	-0.1	-0.2	0.0		
8	7.4	-0.2	-0.2	-0.1		
9	7.5	-0.5	-0.6	-0.6		
10	7.8	-0.8	-0.7	-0.6		
11	7.2	0.2	-0.1	-0.1		
12	7.3	-0.3	-0.3	-0.3		
13	7.1	-0.2	-0.1	-0.1		
14	7.1	0.0	0.0	0.0		
15	6.8	0.1	0.2	0.2		
16	7.1	-0.2	0.0	-0.1		
17	7.1	-0.3	-0.4	-0.4		
18	6.9	-0.1	-0.1	0.1		
19	6.9	-0.1	0.2	0.2		
20	6.9	0.0	0.1	0.1		
21	7.1	0.0	0.1	0.2		
22	6.9	0.0	0.3	0.3		
23	6.9	-0.1	0.1	0.1		
24	6.9	0.0	0.2	0.2		
25	7.5	-0.5	-0.3	-0.1		
MAX	7.8	0.2	0.3	0.3		
MIN	6.8	-0.8	-0.7	-0.6		
AVG	7.2	-0.1	-0.1	0.0		
STD	0.2	0.2	0.3	0.2		
Open	0	0	0	0		
Tech	MOB	MOB	MOB	MOB		
Equip ID	1125	1125	673	673		
	1219	1219	1219	1219		



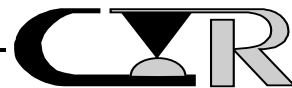
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Low Level Contact Resistance						
Project:	206273-2				Spec:	EIA 364, TP23
Customer:	Samtec				Subgroup:	B
Product:	SFM-125-02-S-D-A/TFM-125-02-S-D-A				File #:	206273-280
Description:	ID# 80					
Open circuit voltage:	20mv			Current:	100ma	
Delta values units: milliohms						
Temp °C	22	22	22	22		
R.H. %	58	53	52	52		
Date:	13Jul06	14Jul06	07Aug06	07Aug06		
Pos. ID	Initial	25X	14D MFG	1X		
1	7.9	0.4	1.2	1.2		
2	7.7	-0.1	0.2	0.4		
3	7.6	0.1	0.5	0.6		
4	7.7	-0.2	0.0	0.4		
5	7.7	-0.2	0.2	0.1		
6	7.8	-0.3	-0.1	-0.2		
7	7.7	-0.2	0.4	0.2		
8	7.6	0.0	0.2	0.3		
9	7.7	-0.2	0.0	0.1		
10	7.5	-0.2	0.2	0.0		
11	7.9	-0.2	-0.1	-0.3		
12	7.7	-0.3	-0.2	-0.1		
13	7.5	0.0	0.1	0.3		
14	7.5	-0.1	0.2	0.0		
15	7.3	0.0	0.2	0.2		
16	7.5	-0.2	0.3	1.2		
17	7.5	-0.1	0.3	0.3		
18	7.3	1.2	1.4	1.0		
19	7.3	-0.2	0.0	0.3		
20	7.7	-0.3	-0.1	-0.1		
21	7.3	-0.1	0.3	0.3		
22	7.4	-0.1	0.2	0.1		
23	7.3	-0.1	0.4	0.5		
24	7.3	-0.3	0.4	0.2		
25	7.6	-0.4	0.9	0.3		
MAX	7.9	1.2	1.4	1.2		
MIN	7.3	-0.4	-0.2	-0.3		
AVG	7.6	-0.1	0.3	0.3		
STD	0.2	0.3	0.4	0.4		
Open	0	0	0	0		
Tech	MOB	MOB	MOB	MOB		
Equip ID	1125	1125	673	673		
	1219	1219	1219	1219		

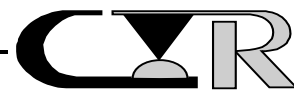


Low Level Contact Resistance						
Project:	206273-2				Spec:	EIA 364, TP23
Customer:	Samtec				Subgroup:	B
Product:	SFM-125-02-S-D-A/TFM-125-02-S-D-A				File #:	206273-281
Description:	ID# 81					
Open circuit voltage:	20mv			Current:	100ma	
Delta values units: milliohms						
Temp °C	22	22	22	22		
R.H. %	58	53	52	52		
Date:	13Jul06	14Jul06	07Aug06	07Aug06		
Pos. ID	Initial	25X	14D MFG	1X		
			Mated			
1	6.7	0.0	0.4	0.2		
2	7.0	0.0	0.1	0.2		
3	6.8	0.0	0.1	0.2		
4	6.6	0.0	0.1	0.2		
5	6.4	-0.1	0.3	0.2		
6	6.8	-0.4	-0.2	-0.1		
7	6.7	0.0	0.3	0.0		
8	6.9	-0.5	-0.1	-0.2		
9	6.7	-0.2	0.1	0.1		
10	6.8	-0.6	-0.1	0.0		
11	7.1	-0.3	-0.2	-0.2		
12	7.0	-0.2	-0.2	-0.2		
13	6.7	-0.6	-0.2	-0.3		
14	6.6	-0.3	0.0	0.0		
15	6.1	-0.3	0.3	0.3		
16	6.5	-0.3	0.1	0.1		
17	6.2	-0.3	0.1	0.0		
18	6.2	-0.2	0.4	0.5		
19	6.2	-0.2	0.3	0.4		
20	6.4	0.2	0.2	0.2		
21	6.5	0.0	0.2	0.3		
22	6.5	-0.1	0.2	0.0		
23	6.2	0.1	0.3	0.2		
24	6.5	-0.3	0.5	0.2		
25	6.2	0.1	0.4	0.5		
MAX	7.1	0.2	0.5	0.5		
MIN	6.1	-0.6	-0.2	-0.3		
AVG	6.6	-0.2	0.1	0.1		
STD	0.3	0.2	0.2	0.2		
Open	0	0	0	0		
Tech	MOB	MOB	MOB	MOB		
Equip ID	1125	1125	673	673		
	1219	1219	1219	1219		



### Low Level Contact Resistance

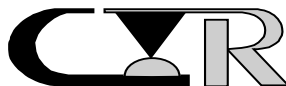
<b>Low Level Contact Resistance</b>					
Project:	206273-2			Spec:	EIA 364, TP23
Customer:	Samtec			Subgroup:	B
Product:	SFM-125-02-S-D-A/TFM-125-02-S-D-A			File #:	206273-282
Description:	ID# 82				
Open circuit voltage:	20mv			Current:	100ma
Delta values units: milliohms					
Temp °C	22	22	22	22	
R.H. %	58	53	52	52	
Date:	13Jul06	14Jul06	07Aug06	07Aug06	
Pos. ID	Initial	25X	14D MFG	1X	
			Mated		
1	7.7	0.0	0.0	-0.1	
2	7.6	-0.1	0.0	-0.1	
3	7.8	-0.2	-0.3	-0.2	
4	7.4	-0.2	0.0	0.1	
5	7.2	0.0	0.1	0.0	
6	7.4	-0.1	0.1	0.1	
7	7.5	0.0	0.5	0.0	
8	7.5	-0.1	0.0	-0.1	
9	7.6	-0.1	0.1	0.2	
10	7.5	-0.2	0.0	0.0	
11	7.4	-0.2	-0.1	-0.1	
12	7.4	-0.3	0.0	0.0	
13	7.3	-0.3	0.0	0.0	
14	7.2	-0.2	0.1	0.0	
15	7.2	-0.1	0.2	0.2	
16	7.3	-0.1	0.3	0.3	
17	7.5	-0.3	0.2	0.0	
18	7.5	-0.2	0.1	-0.1	
19	7.1	-0.2	0.2	0.1	
20	7.3	0.0	0.1	0.2	
21	7.4	0.0	0.1	-0.1	
22	7.2	-0.2	0.2	0.2	
23	7.4	-0.2	0.1	-0.1	
24	7.3	-0.2	0.2	0.0	
25	7.2	-0.3	-0.1	0.4	
MAX	7.8	0.0	0.5	0.4	
MIN	7.1	-0.3	-0.3	-0.2	
AVG	7.4	-0.1	0.1	0.0	
STD	0.2	0.1	0.1	0.1	
Open	0	0	0	0	
Tech	MOB	MOB	MOB	MOB	
Equip ID	1125	1125	673	673	
	1219	1219	1219	1219	



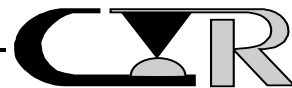
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Low Level Contact Resistance						
Project:	206273-2				Spec:	EIA 364, TP23
Customer:	Samtec				Subgroup:	B
Product:	SFM-125-02-S-D-A/TFM-125-02-S-D-A				File #:	206273-283
Description:	ID# 83					
Open circuit voltage:	20mv			Current:	100ma	
Delta values units: milliohms						
Temp °C	22	22	22	22		
R.H. %	58	53	52	52		
Date:	13Jul06	14Jul06	07Aug06	07Aug06		
Pos. ID	Initial	25X	14D MFG	1X		
			Mated			
1	7.5	-0.1	0.5	-0.4		
2	7.7	-0.3	-0.2	-0.3		
3	7.6	-0.4	0.2	-0.1		
4	7.7	-0.4	-0.1	-0.2		
5	7.6	-0.3	0.1	0.0		
6	7.5	-0.3	0.0	0.0		
7	7.0	-0.1	0.6	0.2		
8	7.4	-0.3	0.0	0.0		
9	7.4	-0.1	0.0	-0.1		
10	7.4	-0.3	-0.1	-0.1		
11	7.3	-0.1	0.0	0.1		
12	7.3	-0.3	-0.2	-0.2		
13	7.8	-0.6	-0.5	-0.5		
14	7.3	-0.3	-0.2	0.0		
15	6.9	-0.2	0.1	0.1		
16	7.4	-0.6	-0.3	-0.2		
17	6.9	-0.1	0.1	0.1		
18	7.1	0.1	0.2	0.3		
19	6.9	0.1	0.4	0.6		
20	7.4	-0.1	0.4	0.3		
21	7.1	0.0	0.5	0.6		
22	7.1	0.0	0.4	0.1		
23	7.3	-0.2	0.6	0.2		
24	7.2	-0.1	0.6	0.2		
25	7.0	0.2	0.7	0.4		
MAX	7.8	0.2	0.7	0.6		
MIN	6.9	-0.6	-0.5	-0.5		
AVG	7.3	-0.2	0.2	0.0		
STD	0.3	0.2	0.3	0.3		
Open	0	0	0	0		
Tech	MOB	MOB	MOB	MOB		
Equip ID	1125	1125	673	673		
	1219	1219	1219	1219		



Low Level Contact Resistance						
Project:	206273-2				Spec:	EIA 364, TP23
Customer:	Samtec				Subgroup:	B
Product:	SFM-125-02-S-D-A/TFM-125-02-S-D-A				File #:	206273-284
Description:	ID# 84					
Open circuit voltage:	20mv			Current:	100ma	
Delta values units: milliohms						
Temp °C	22	22	22	22		
R.H. %	58	53	52	52		
Date:	13Jul06	14Jul06	07Aug06	07Aug06		
Pos. ID	Initial	25X	14D MFG	1X		
			Mated			
1	7.1	-0.3	0.0	0.0		
2	6.8	0.0	0.1	0.3		
3	7.4	-0.2	-0.2	-0.2		
4	6.9	0.1	0.0	0.1		
5	7.2	-0.1	0.1	0.1		
6	6.7	0.1	0.1	0.2		
7	6.7	0.1	0.3	0.3		
8	7.1	-0.1	0.1	0.1		
9	6.5	0.1	0.2	0.1		
10	7.0	-0.2	0.1	0.2		
11	6.5	0.1	0.3	0.1		
12	7.3	-0.5	-0.3	-0.2		
13	6.4	-0.1	0.3	0.5		
14	6.5	-0.3	0.3	0.4		
15	6.7	-0.2	0.2	0.2		
16	6.6	-0.3	0.1	0.1		
17	6.6	-0.1	0.0	0.0		
18	6.7	-0.2	0.1	0.3		
19	6.4	-0.1	0.2	0.2		
20	6.9	-0.2	0.1	0.0		
21	6.6	0.0	0.1	0.2		
22	6.6	0.0	0.2	0.4		
23	6.8	0.0	0.2	0.4		
24	6.7	0.0	0.3	0.4		
25	6.9	-0.2	0.1	-0.1		
MAX	7.4	0.1	0.3	0.5		
MIN	6.4	-0.5	-0.3	-0.2		
AVG	6.8	-0.1	0.1	0.2		
STD	0.3	0.2	0.1	0.2		
Open	0	0	0	0		
Tech	MOB	MOB	MOB	MOB		
Equip ID	1125	1125	673	673		
	1219	1219	1219	1219		



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Low Level Contact Resistance						
Project:	206273-2				Spec:	EIA 364, TP23
Customer:	Samtec				Subgroup:	B
Product:	SFM-125-02-S-D-A/TFM-125-02-S-D-A				File #:	206273-285
Description:	ID# 85					
Open circuit voltage:	20mv			Current:	100ma	
Delta values units: milliohms						
Temp °C	22	22	22	22		
R.H. %	58	53	52	52		
Date:	13Jul06	14Jul06	07Aug06	07Aug06		
Pos. ID	Initial	25X	14D MFG	1X		
			Mated			
1	6.8	0.0	0.2	0.1		
2	6.9	0.1	0.2	0.3		
3	6.4	0.2	0.3	0.2		
4	6.7	0.1	0.1	0.3		
5	6.3	0.0	0.1	0.0		
6	6.5	0.0	0.1	0.2		
7	7.1	-0.5	0.1	-0.1		
8	6.8	0.0	0.0	0.0		
9	7.0	-0.2	0.1	0.0		
10	6.8	-0.4	-0.2	-0.2		
11	6.6	0.0	0.1	0.1		
12	6.5	-0.3	0.1	-0.1		
13	6.8	-0.5	0.1	-0.1		
14	6.6	-0.2	0.0	-0.1		
15	6.4	0.1	0.1	0.1		
16	6.7	-0.5	0.0	-0.2		
17	6.6	-0.3	0.2	0.0		
18	6.4	-0.2	0.1	0.0		
19	6.9	0.0	0.4	0.0		
20	6.2	0.1	0.1	0.0		
21	6.5	0.1	0.2	0.3		
22	6.4	0.1	0.2	0.1		
23	6.5	0.1	0.2	0.0		
24	6.6	-0.2	0.1	0.0		
25	7.1	0.1	0.2	0.1		
MAX	7.1	0.2	0.4	0.3		
MIN	6.2	-0.5	-0.2	-0.2		
AVG	6.6	-0.1	0.1	0.0		
STD	0.3	0.2	0.1	0.2		
Open	0	0	0	0		
Tech	MOB	MOB	MOB	MOB		
Equip ID	1125	1125	673	673		
	1219	1219	1219	1219		

